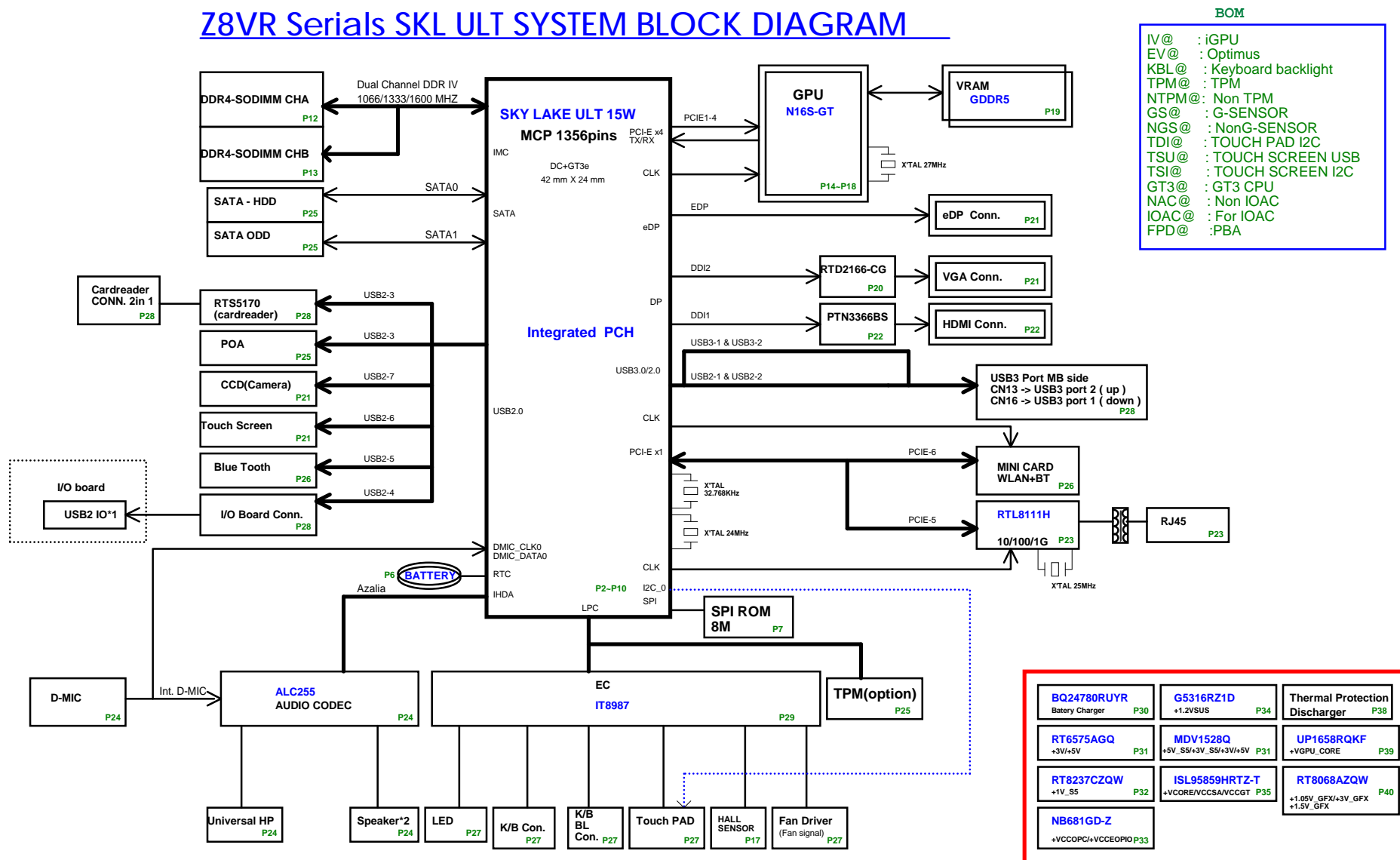
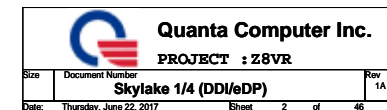
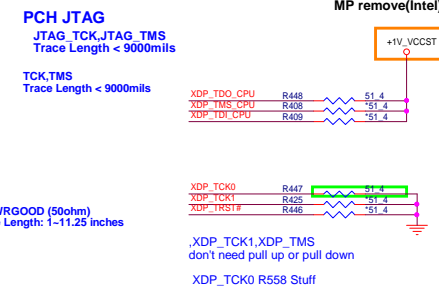


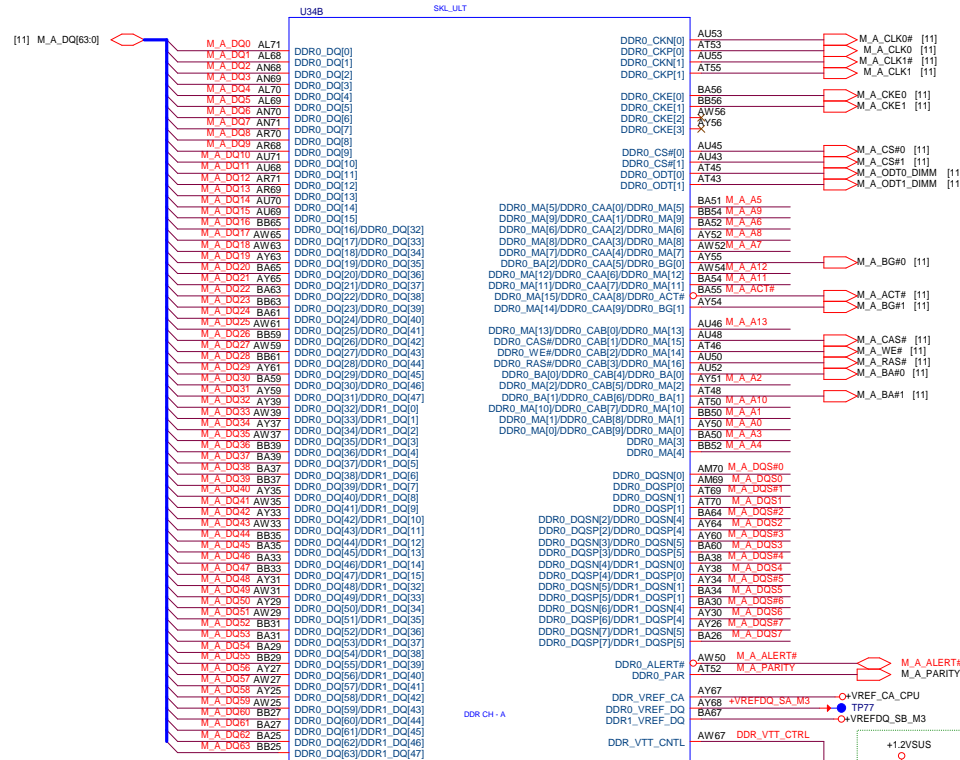
Z8VR Serials SKL ULT SYSTEM BLOCK DIAGRAM



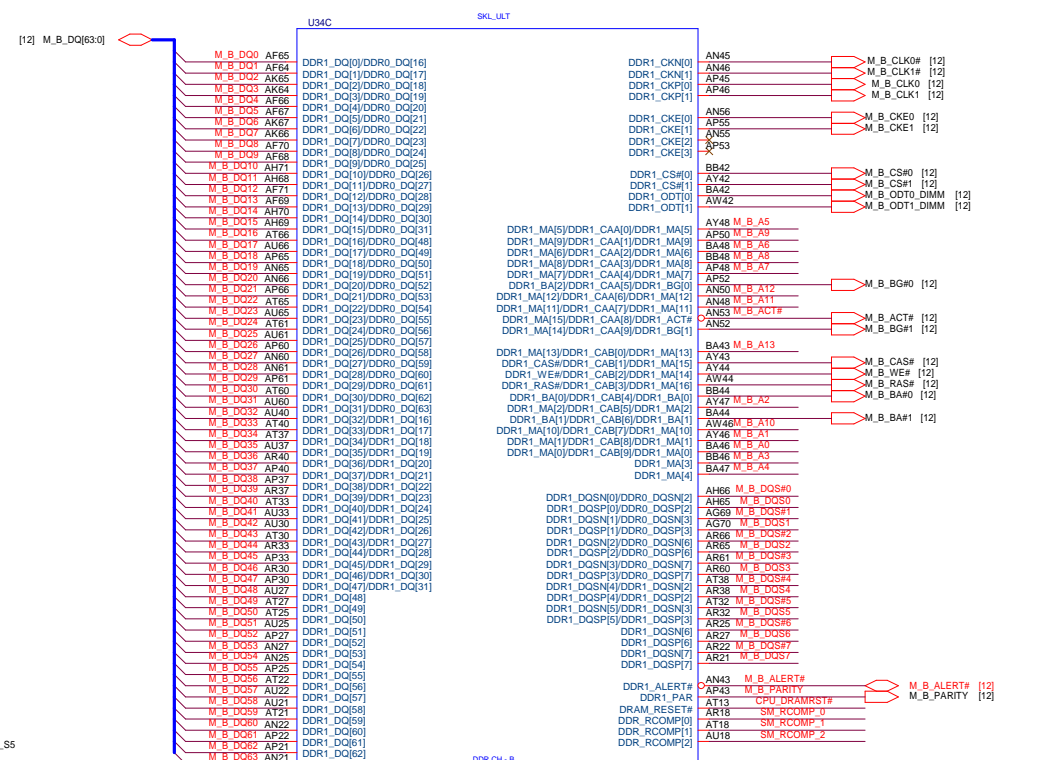


Change Data and DQS to interleave.

SKL ULT (DDR4)



SKL ULT (DDR4)

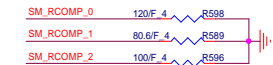
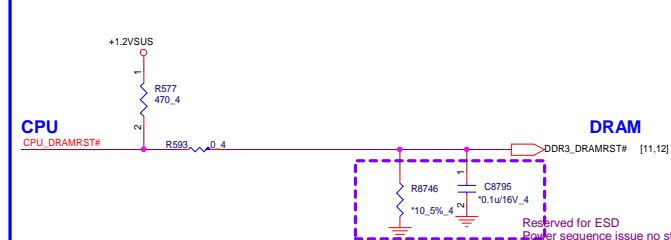


Stuff Q54 for both UMA and GPU in DDR_VTT_CNTL



DRAM COMP

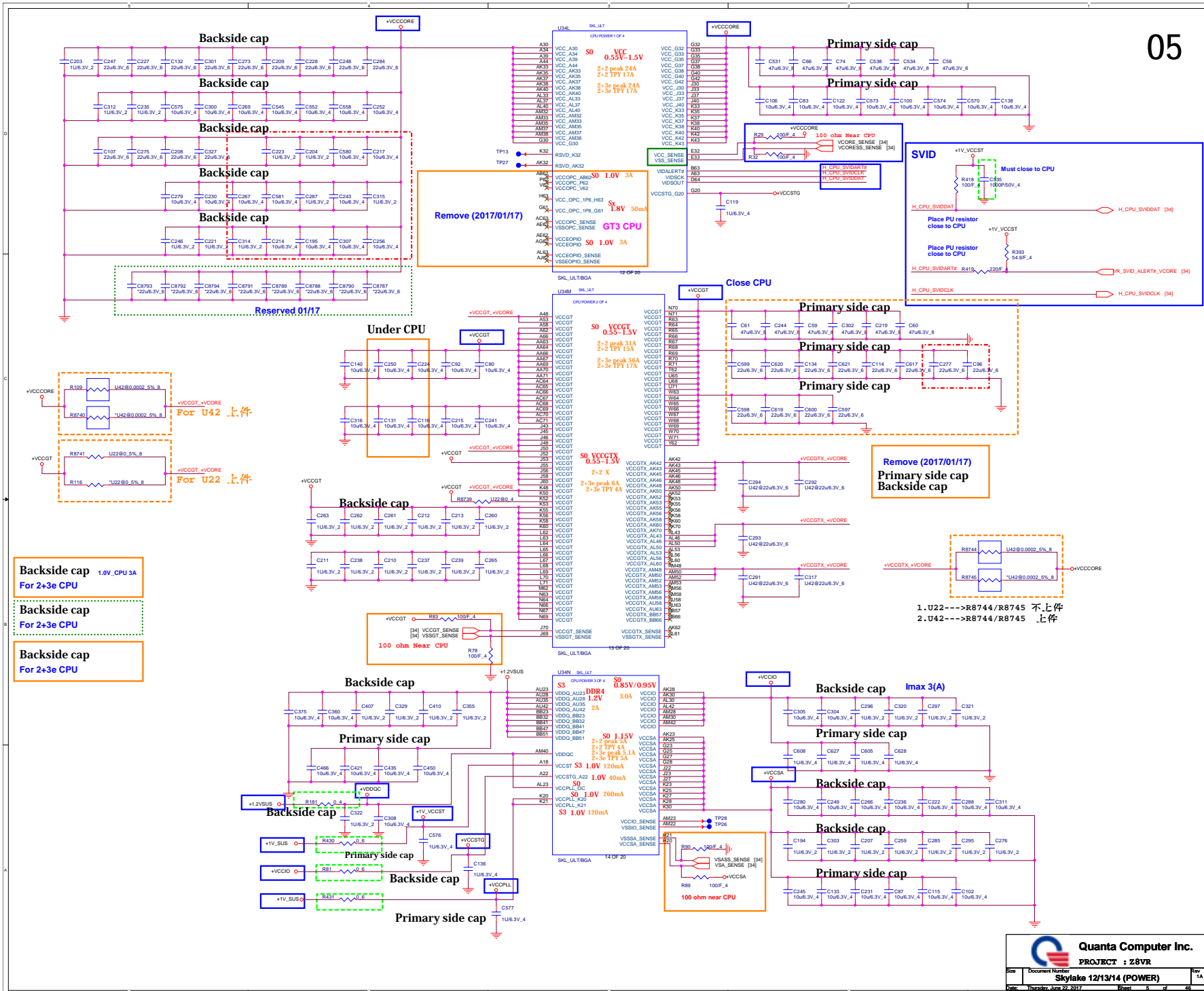
DRAMRST

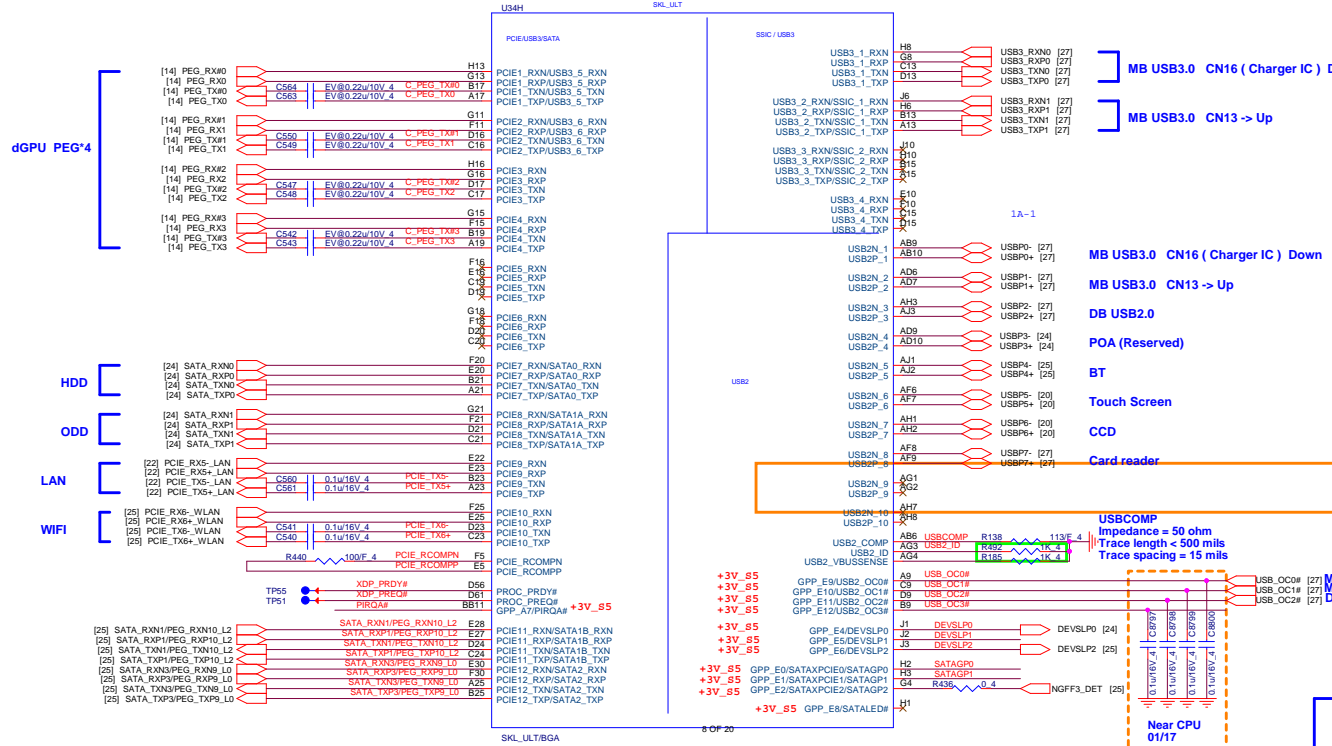


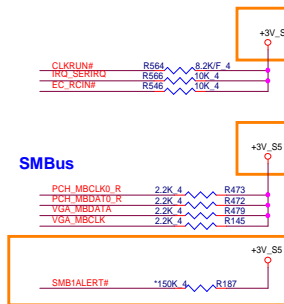
Quanta Computer Inc.

PROJECT : Z8VR

Size	Document Number	Rev
	Skylake 2/3 (DDR3 I/F)	1A
Date:	Thursday, June 22, 2017	Sheet 3 of 46

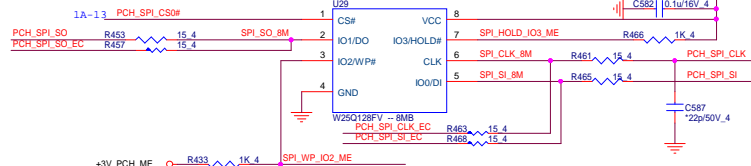






[28] SIO_RCIN# R573 0.4 EC_RCIN#

[24,28] IRQ_SERIRQ   IRQ_SERIRQ



3.3K is original and for no support fast read function

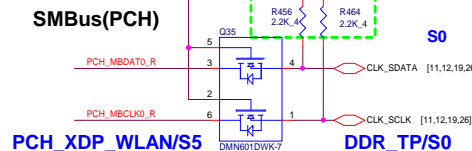
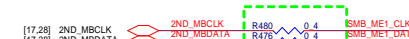
PCH_SPI_IO2 R415 15.4 SPI_WP_IO2_ME

PCH_SPI_IO3 R477 15.4 SPI_HOLD_IO3_ME

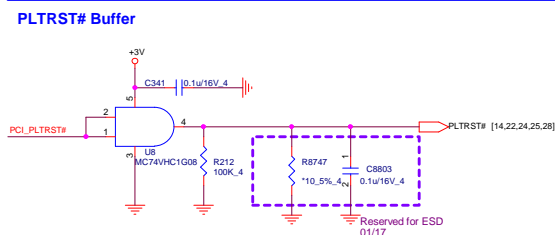
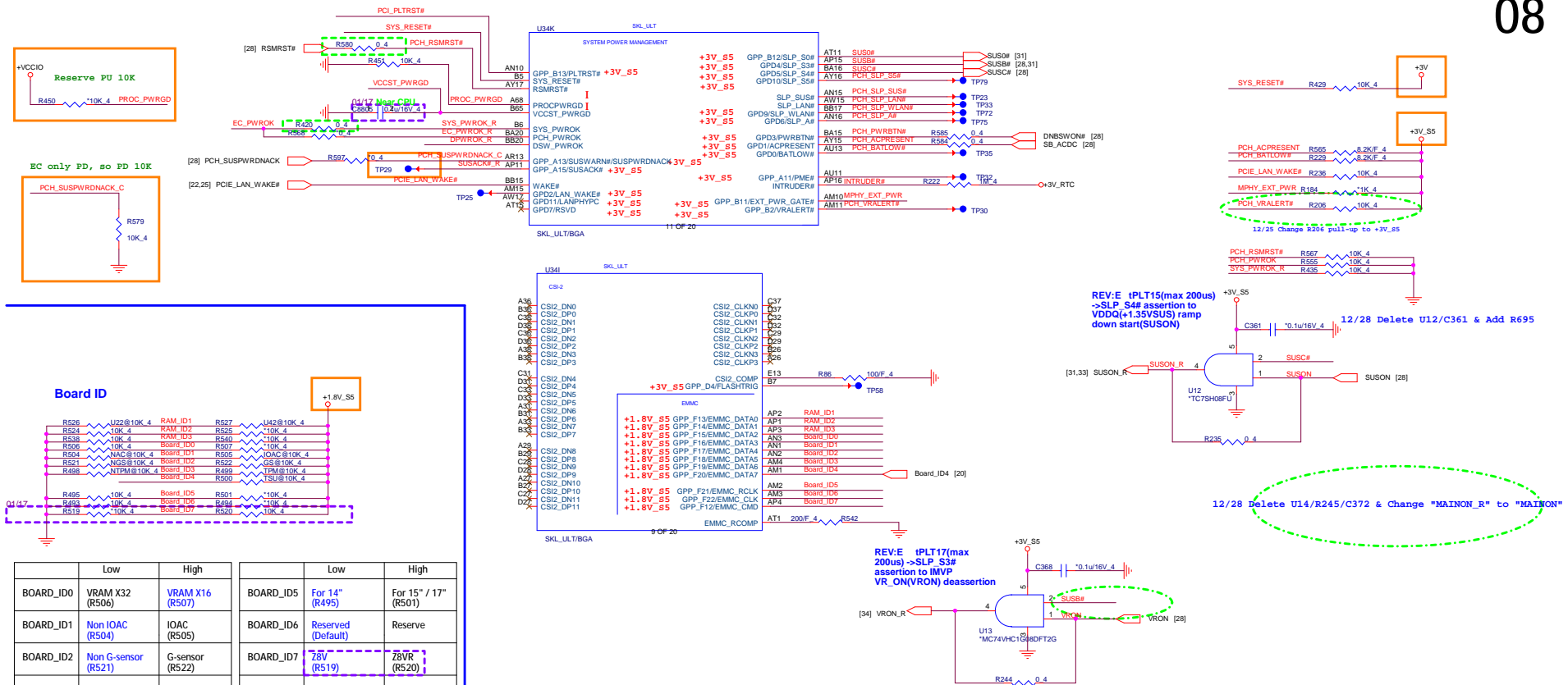
reserve for SPI fast read



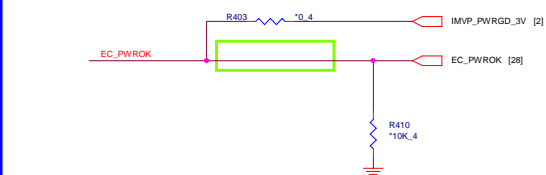
only 0ohm option

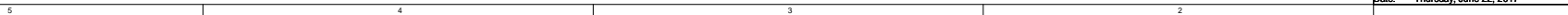
**SMBus(EC)**


EC/S5



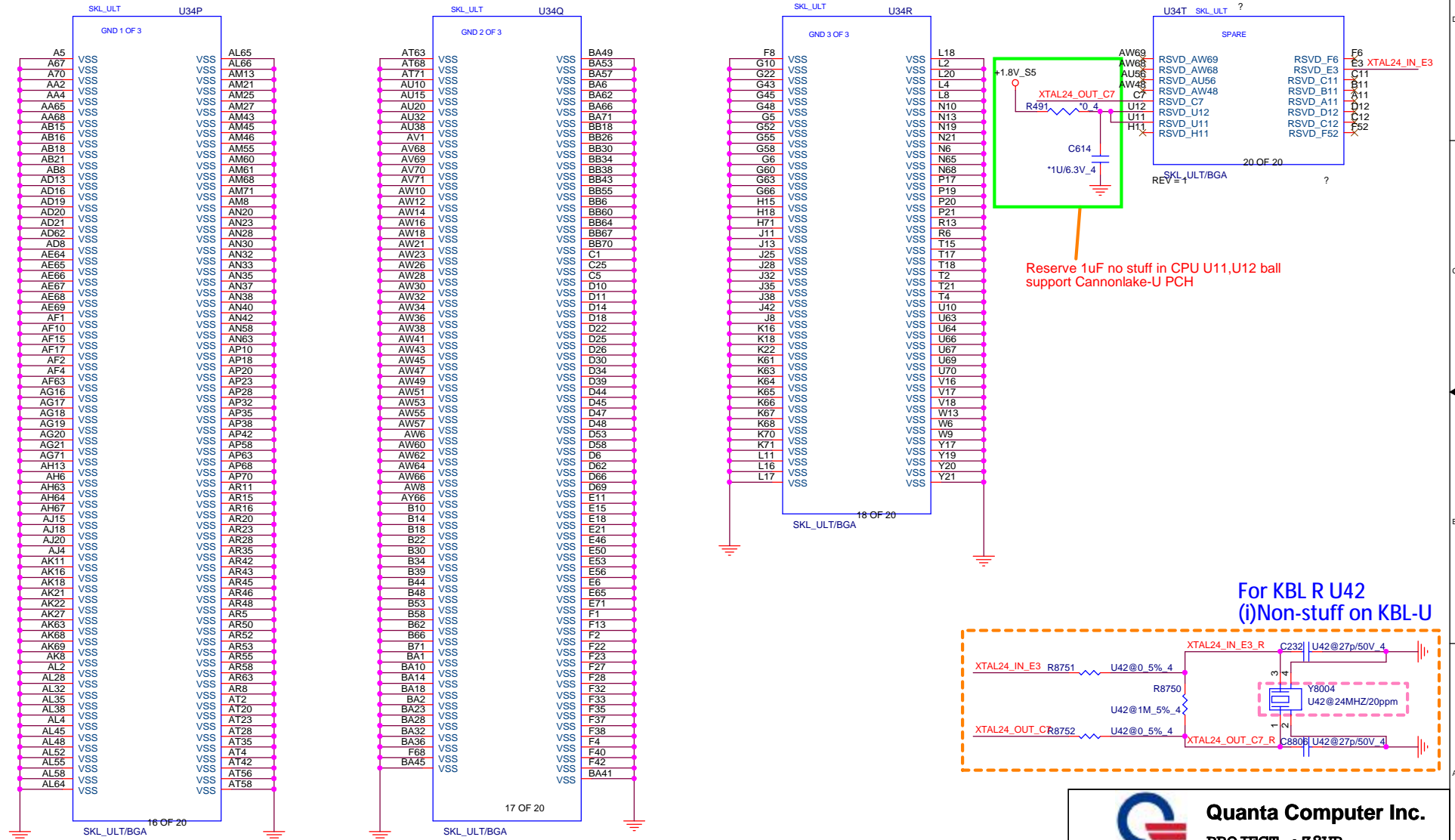
SYSPWOK



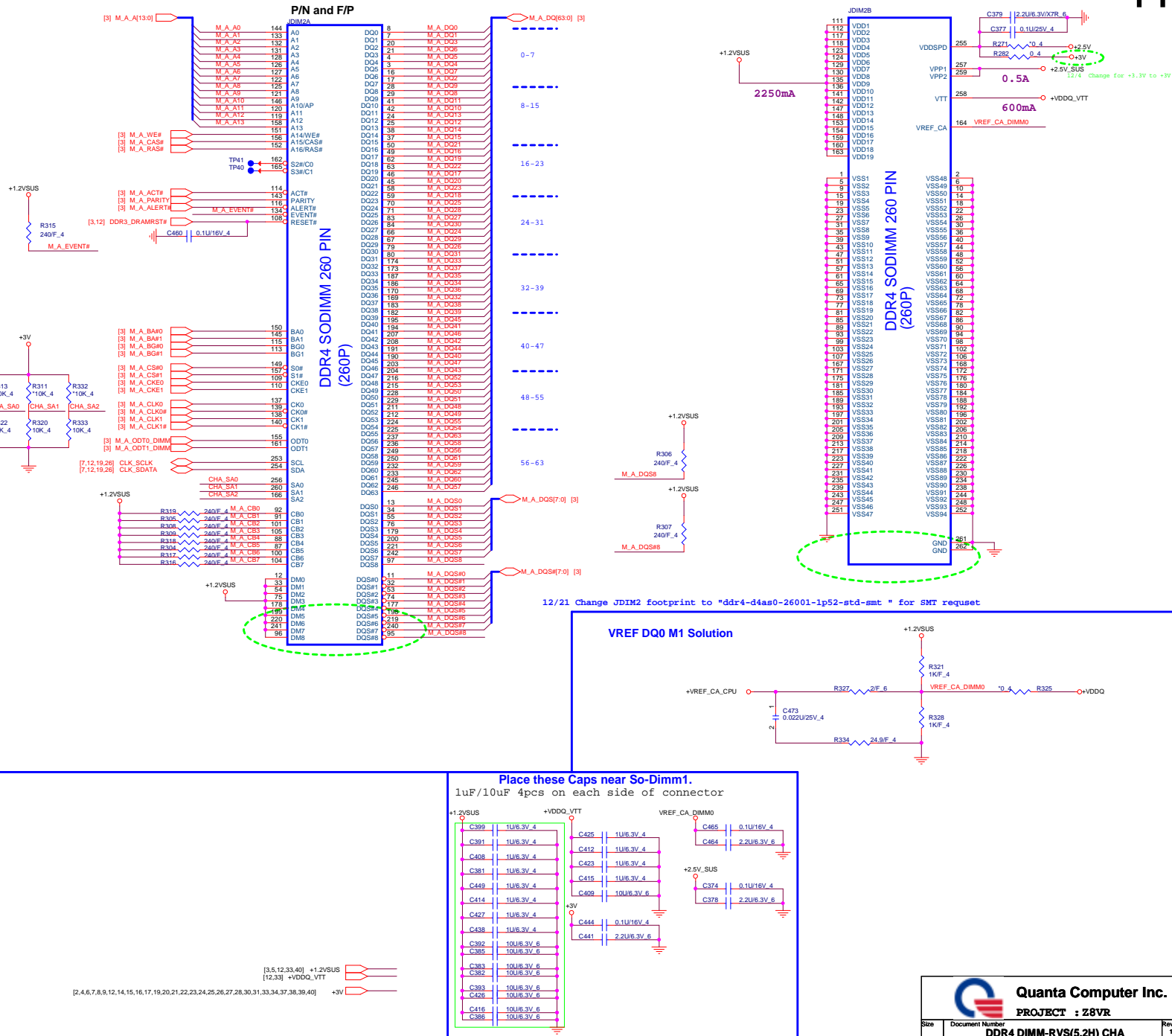


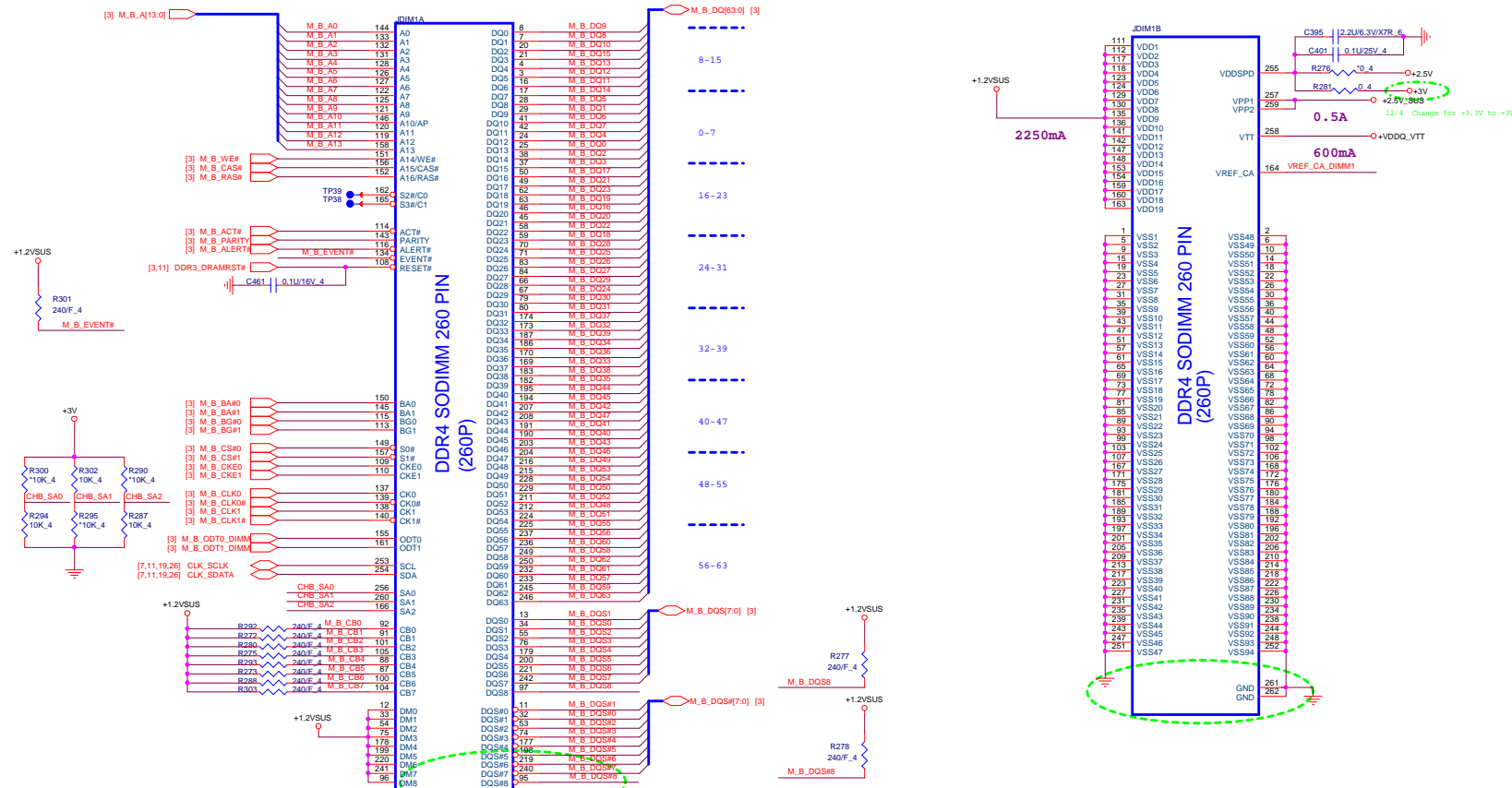
 Quanta Computer Inc. PROJECT : Z8VR		
Size	Document Number	Rev
	Skylake PCH-LP 15/19 (POWER)	1A
Date:	Thursday, June 22 2017	Sheet 9 of 46

Skylake ULT (GND)



For KBL R U42
(i)Non-stuff on KBL-U



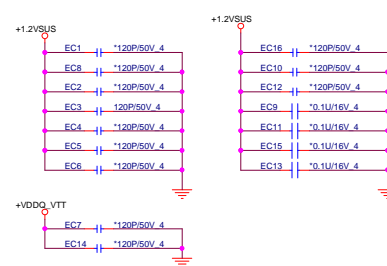


12/21 Change JDIM1 footprint to "ddr4-d4ar0-26001-1p52-rvs-smt " for SMT request

[2,4,6,7,8,9,11,14,15,16,17,19,20,21,22,23,24,25,26,27,28,30,31,33,34,37,38,39,40]

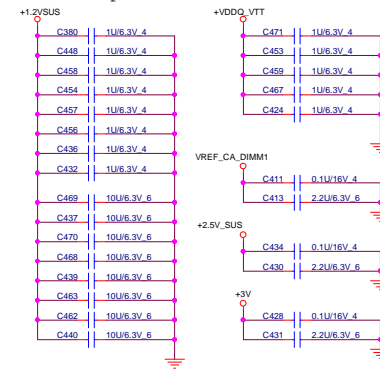
[3,5,11,33,40] +1.2VSUS

For EMI RESERVE

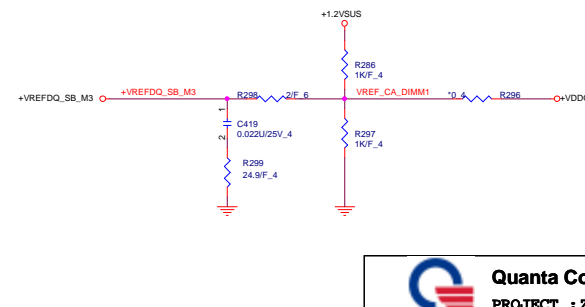


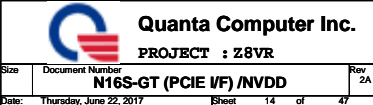
Place these Caps near So-Dimm0.

1uF/10uF 4pcs on each side of connector

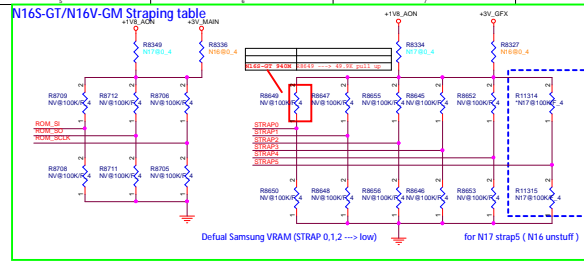


VREF DQ1 M1 Solution









N16S-GT DID=0x1347 [940M]

ROM_SCLK = Stiff 4.99K pull down
 ROM_A0 = Stiff 4.99K pull down
 STRAP0 = Stiff 48.9K pull up
 STRAP1 = NC
 STRAP2 = NC
 STRAP3 = NC
 STRAP4 = NC
 ROM_SI = VRAM Configuration follow below table

N17S-G1-A1 DID=0x1D10 [1040]

ROM_SI = Stiff 100K pull up
 ROM_A0 = Stiff 48.9K pull up
 ROM_SCLK = Stiff 100K pull up and Stiff 100K pull down
 STRAP0 = VRAM Configuration follow below table
 STRAP1 = VRAM Configuration follow below table
 STRAP2 = Stiff 100K pull down
 STRAP3 = Stiff 100K pull down
 STRAP4 = Stiff 100K pull down

Note: GC6 2.0 is supported by N16x GPU in the GB28, GB48-128, and GB38-256 packages.

Logical Strap Bit Mapping

	PU-VDD	PD
4.99K	1000	0000
10K	1001	0001
15K	1010	0010
20K	1011	0011
24.9K	1100	0100
30.1K	1101	0101
34.8K	1110	0110
45.3K	1111	0111

N16S-GT/N16V-GM Strapping table

ROM_SI N16S-GT [940M]
 2G Hynix 128Mx16 -> 34.8K PD
 2G Micron 128Mx16 -> 45.3K PD
 2G Samsung 128Mx16 -> 4.99K PU
 4G Hynix 256Mx16 -> 30.1K PU Single Rank
 4G Hynix 256Mx16 -> 24.9K PU Dual Rank
 4G Micron 256Mx16 -> 10K PD
 4G Samsung 256Mx16 -> 15K PD

ROM_SO N16S-GT -> 4.99K PD
 ROM_SCLK N16S-GT -> 4.99K PD
 STRAP0 N16S-GT -> 48.9K PU

N16S-GT-A2 PN : AJ0N16S0T44

N17S-G1-A1 PN : AJ0N17S0T00

GPIO ASSIGNMENTS

GPIO	I/O	PIN	USAGE
0	IN	FB_CLAMP_MON	FB Clamp monitor (GC6 1.0)
0	OUT	GC6_FB_EN	GC6 FB Enable (GC6 2.0)
5	OUT	+3V_MAIN_EN	Enable GC6 +3V_MAIN
6	OUT	FB_CLAMP_REQ#	Active low FB Clamp toggle request (GC6 1.0)
6	IN	DGPU_EVENT#	DGPU EVENT from CPU (GC6 2.0)
8	OUT	VGA_OVTH	ACTIVE LOW THERMAL OVER TEMP
9	OUT	ALERT	ACTIVE LOW THERMAL ALERT
11	OUT	PWR_VID	GPU CORE_VDD PWM Control signal
12	IN	PWR_LEVEL	AC Power detect or power supply overdraw input
13	OUT	PSI	Phase Shedding

N16S-GT VRAM Configuration Table

ROM_SI

RAMCFG [3:0]	DESCRIPTION	1.35V DDR5	Vendor	Vendor PIN	ROM_SI	STN B/S
0000 0x0	DDR5 256Mx32, 64bit, 8Gb, 2500MHz		SAMSUNG B-die	K4G80325FB-HC03	PD 4.99K ohm	AKG5SGDT502
0000 0x0	DDR5 256Mx32, 64bit, 8Gb, 3000MHz		SAMSUNG B-die	K4G80325FB-HC28	PD 4.99K ohm	AKG5SGDT518
0001 0x1	DDR5 256Mx32, 64bit, 8Gb, 2500MHz		Micron A-die	MT51J256M32HF-60-A	PD 10K ohm	AKG5SGUTL04
0001 0x1	DDR5 256Mx32, 64bit, 8Gb, 3000MHz		Micron A-die	MT51J256M32HF-70-A	PD 10K ohm	AKG5SGUTL15
0101 0x5	DDR5 256Mx32, 64bit, 8Gb, 2500MHz		HYNIX M-die	H5GCH24MJR-T2C	PD 30.1K ohm	AKG5SGUTW04
0101 0x5	DDR5 256Mx32, 64bit, 8Gb, 3000MHz		HYNIX M-die	H5GCH24MJR-ROC	PD 30.1K ohm	AKG5SGUTW06

N17S-G1-A1 VRAM Configuration Table

STRAP0, STRAP1, STRAP2

RAMCFG [3:0]	DESCRIPTION	1.35V DDR5	Vendor	Vendor PIN	STRAP0	STRAP1	STRAP2	STN B/S
0000 0x0	DDR5 256Mx32, 64bit, 8Gb, 3000MHz		SAMSUNG B-die	K4G80325FB-HC28	PD 100K ohm	PD 100K ohm	PD 100K ohm	AKG5SGDT518
0001 0x1	DDR5 256Mx32, 64bit, 8Gb, 3000MHz		Micron A-die	MT51J256M32HF-70-A	PU 100K ohm	PD 100K ohm	PD 100K ohm	AKG5SGUTL15
0010 0x2	DDR5 256Mx32, 64bit, 8Gb, 3000MHz		HYNIX M-die	H5GCH24MJR-ROC	PD 100K ohm	PU 100K ohm	PD 100K ohm	AKG5SGUTW06

Non-mirror, MF=0 Channel A
<0-31>

Mirror, MF=1

Channel A
<32-63>

DQA24~31

DQA16~23

DQA8~15

DQA0~7

DQA32~39

DQA40~47

DQA48~55

DQA56~63

KB OnlyA

GDDR5 Mode H Mapping

< 0-31 >	< 32-63 >	Memory
CHD0	CHD16	CS*
CHD1	CHD17	A1_BA3
CHD2	CHD18	A2_BA0
CHD3	CHD19	A1_BA2
CHD4	CHD20	A5_BA1
CHD5	CHD21	WB*
CHD6	CHD22	A7_A8
CHD7	CHD23	A6_A11
CHD8	CHD24	ABT*
CHD9	CHD25	A12_RP0
CHD10	CHD26	A1_A10
CHD11	CHD27	A1_A9
CHD12	CHD28	RA0*
CHD13	CHD29	RST*
CHD14	CHD30	CSB*
CHD15	CHD31	CAB*

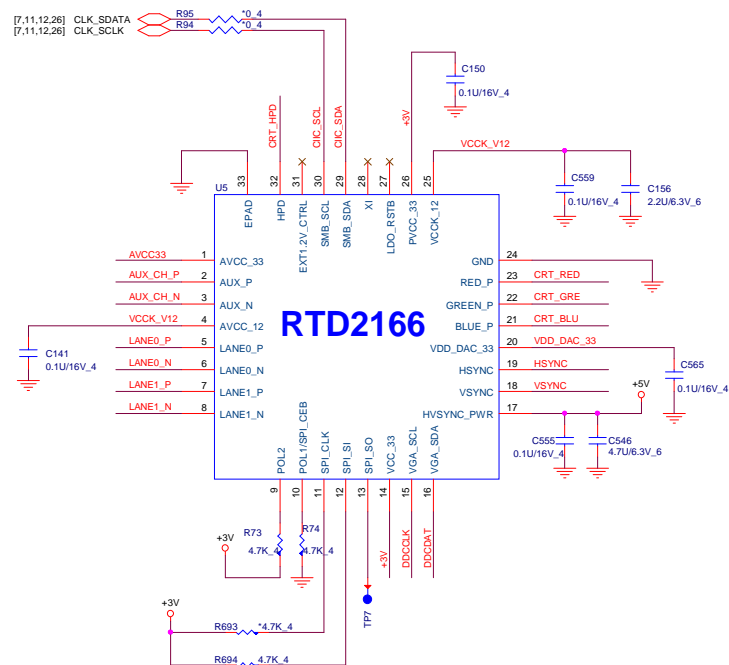
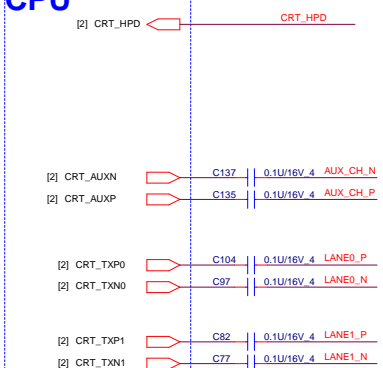
RST PD place @ the end of daisy-chain.

DP TO VGA

Power



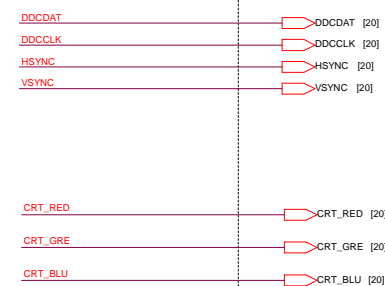
CPU



Note:

- 1- C1,C3,C4,C5,C11,C16, C21 should be placed close to chip
- 2- C5 should be X5R material
- 3- R6, R7, R8 should be 75 ohm with +/-1%
- 4- Suggest to connect Pin 29 and Pin 30 to PCH SMBUS for debug purpose.
- 5- This configuration is for internal ROM mode and using embedded LDO mode.

VGA



[2,4,6,7,8,9,11,12,14,15,16,17,20,21,22,23,24,25,26,27,28,30,31,33,34,37,38,39,40] +3V
[20,21,23,24,26,30,37] +5V

RTD2166 integrate 25 HSYNC/VSYNC buffer inside IC

12/24 Delete R449

12/18 Change R412 to 470ohm for vendor request

[19] HSYNC

U30

M74VHC1G11

OE#

VCC

A

Y

GND

R458

R412

R421

CRTHSYNC

5V

C562

0.1u/16V_4

12/24 Delete R396

12/18 Change R399 to 470ohm for vendor request

[19] VSYNC

U26

M74VHC1G11

OE#

VCC

A

Y

GND

R392

R399

R406

CRTVSYNC

5V

C533

0.1u/16V_4

Red-Layout

Realtek FAE suggest close to connector

[illegible][illegible]

1st:AL009249000 -- BCD
2nd:AL009132001 -- ANC

EDP_VDD_EN

3V

C20
1uF/3.3V_4

R30
0.4

EDP_VDD_EN_R 3

R31
100K_4

U2
GS245A11U

IN 6

IN 4

ON/OFF 5

OUT 1

GND 2

GND 5

C7
0.1u/16V_4

C12
2.2u/50V_8

C6
0.1u/16V_4

C9
0.01u/50V_4

C18
22u/6.3V_8

LCDVCC

1st : AL005245000---GMT

2nd : AL007553000---UPI

[illegible]

HDMI

<HDM>

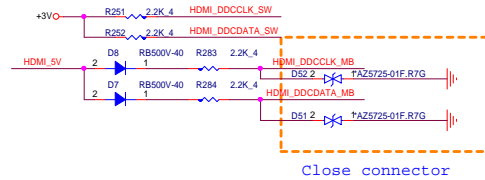
OE_N	DDC_EN	HPD_SINK	Source output	PTN3366 power mode
LOW	HIGH	HIGH	source active	Active mode: DDC active
LOW	LOW	LOW	don't care	Standby mode
HIGH	LOW	don't care	don't care	Ultra low-power mode

From PCH

HDMI-detect

S5 input high

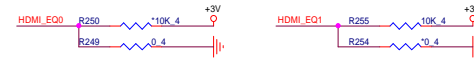
S0



Close connector

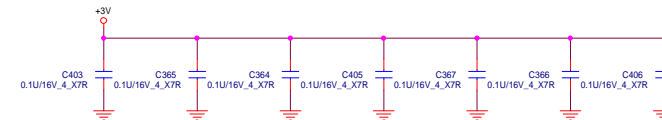
Power trace tracking

[2,4,6,7,8,9,11,12,14,15,16,17,19,20,22,23,24,25,26,27,28,30,31,33,34,37,38,39,40]
[19,20,23,24,26,30,37]

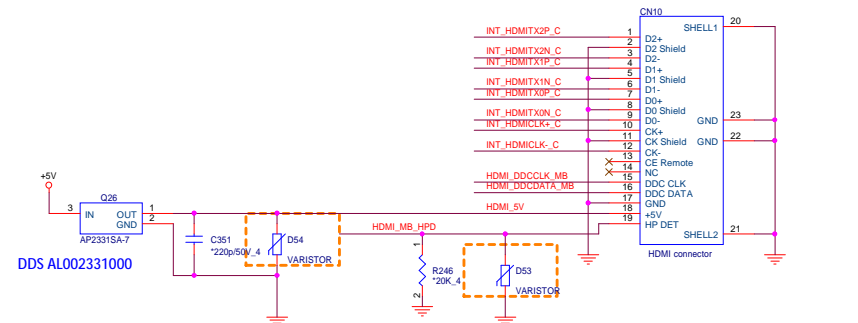
+3V
+5V

Inputs	EQ0	Equalization for 3 Gbit/s
EQ1 short to GND	short to GND	0 dB
short to GND	short to Vcc	2 dB
short to VDD	short to GND	4 dB
short to VDD	short to Vcc	6 dB

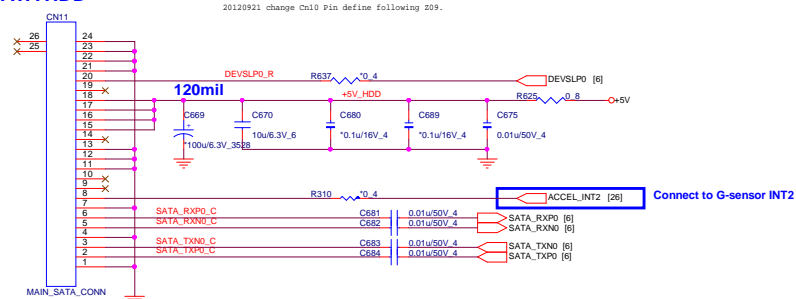
21



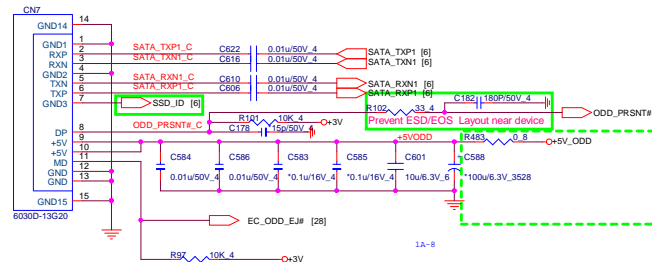
HDMI connector



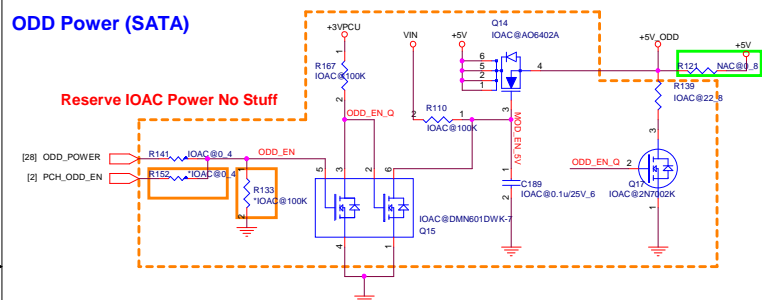
SATA HDD



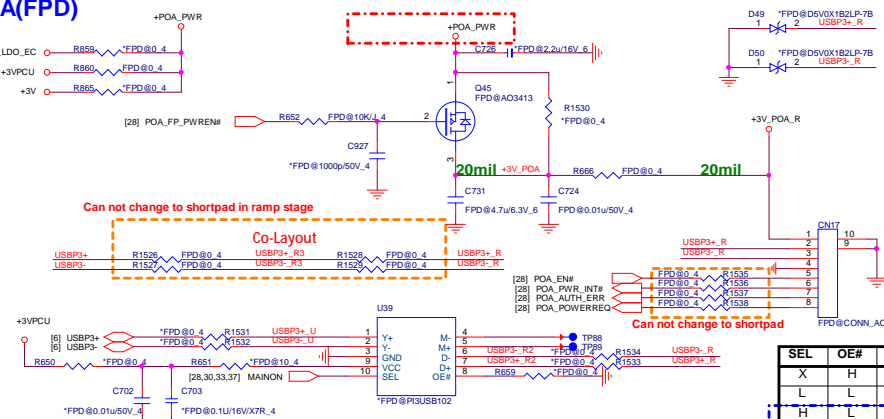
SATA ODD Connector



ODD Power (SATA)



POA(FPD)



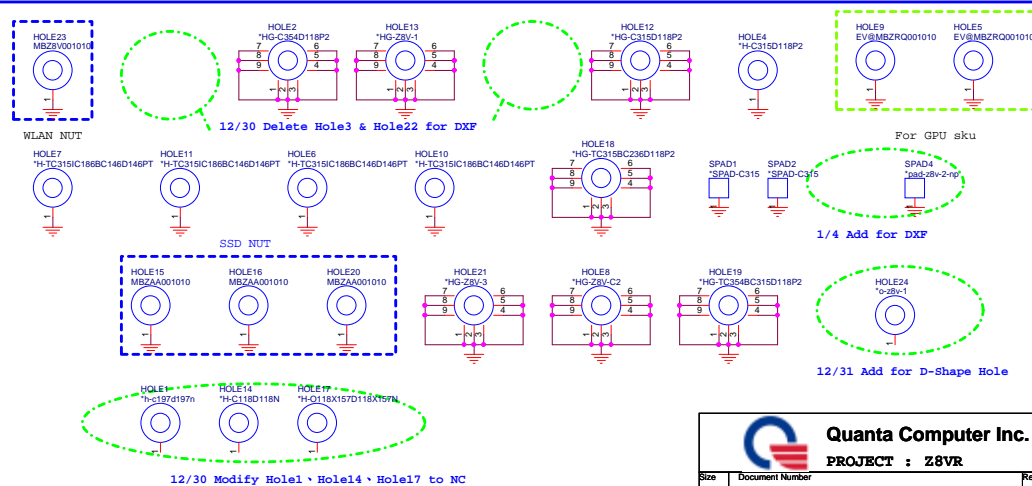
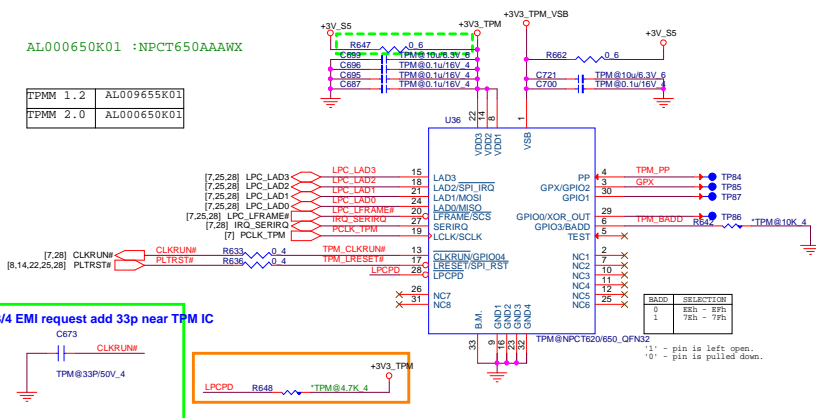
Spec define: High Active

TPM NPCT650 (TPM)

SP@ BOM周邊上NPCT650
A,B,C P/N:AL009655K01(SLB9655TT1.2- FW4.31)
RAMP P/N: AL000650K01 (NPCT650AAAWX)

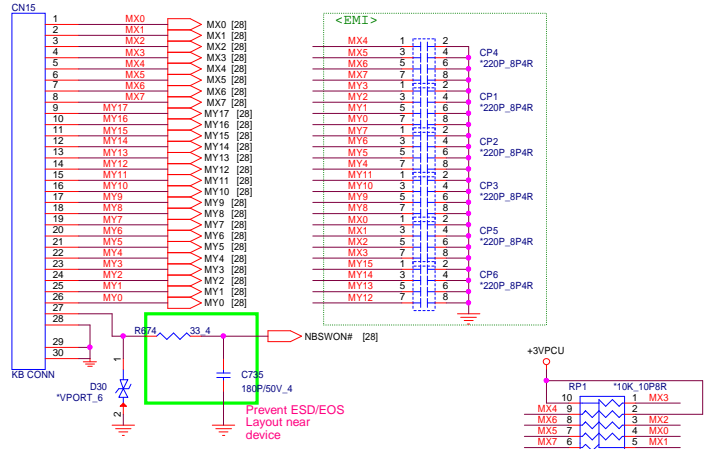
AL000650K01 :NPCT650AAAWX

TPMM 1.2	AL009655K01
TPMM 2.0	AL000650K01

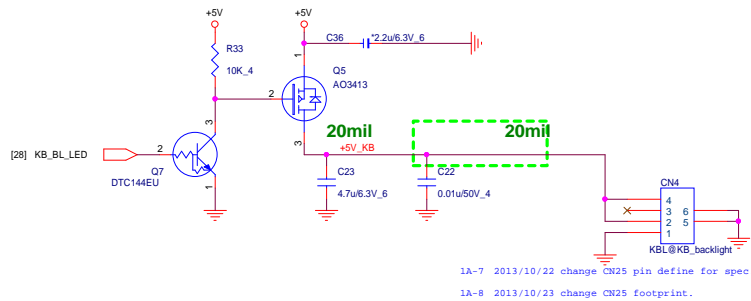




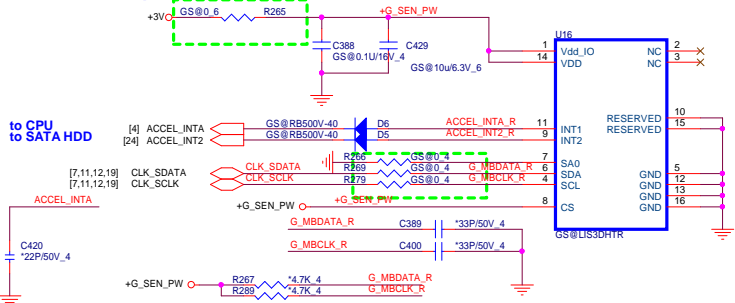
KEYBOARD (KBC)



KB_BL LED (KBC)

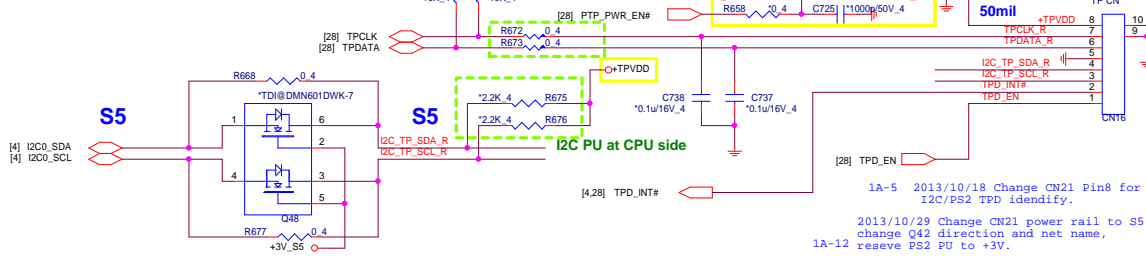


G-sensor(ACS)



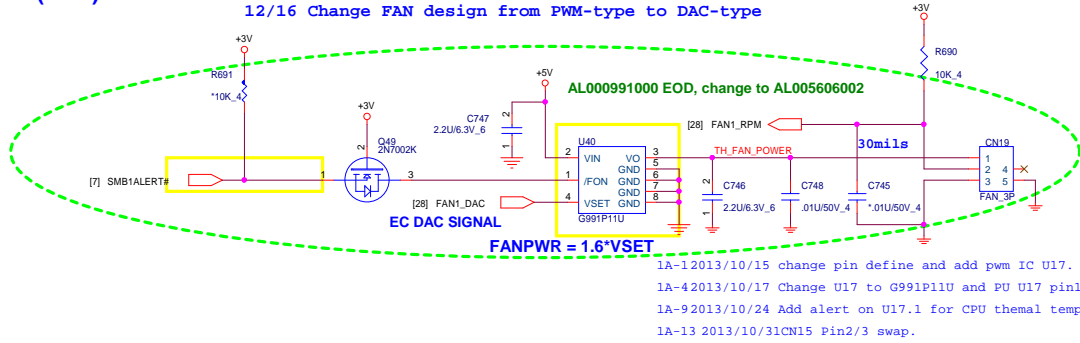
TOUCHPAD BOARD CONN (TPD I2C/PS2 co-lay)

TPD->100kHz, TS=400kHz
Intel design guide suggestion
MCP PIN 10u.
Per inch 3u TS=3x5inch.
400kHz±10-100u =2.4-0.4k.
100kHz 10-100u=9k-1k.



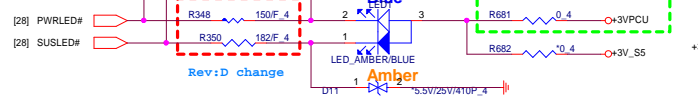
CPU FAN (THM)

12/16 Change FAN design from PWM-type to DAC-type

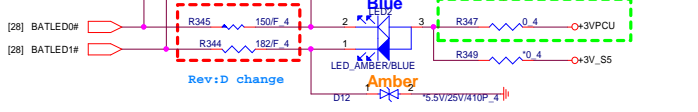


POWER LED(UIF)

Power LED

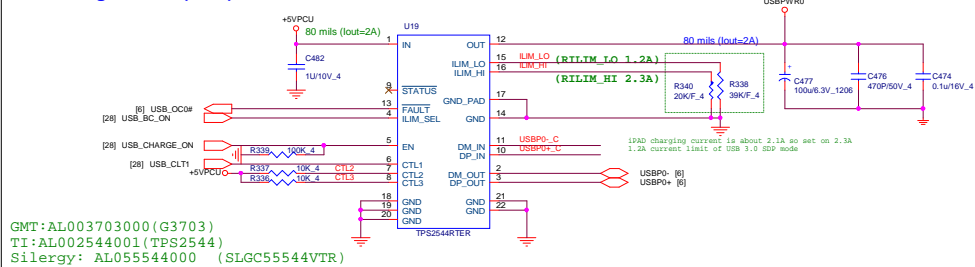


Battery



USB Charger to 3.0 (UBC)

27



	CTL1	CTL2	CTL3	ILIM_SE
SDP	1	1	1	0
CDP	1	1	1	1
DCP	0	1	1	X

RILIM_LO is optional and the RILIM_LO pin may be left unconnected if the following conditions are met:

1. ILIM_SEL is always set high
2. Load Detection - Port Power Management is not used
3. Mouse / Keyboard wake function is not used

If conditions 1 and 2 are met but the mouse / keyboard wake function is also desired, it is recommended to use RILIM_LO < 80.6 kΩ.

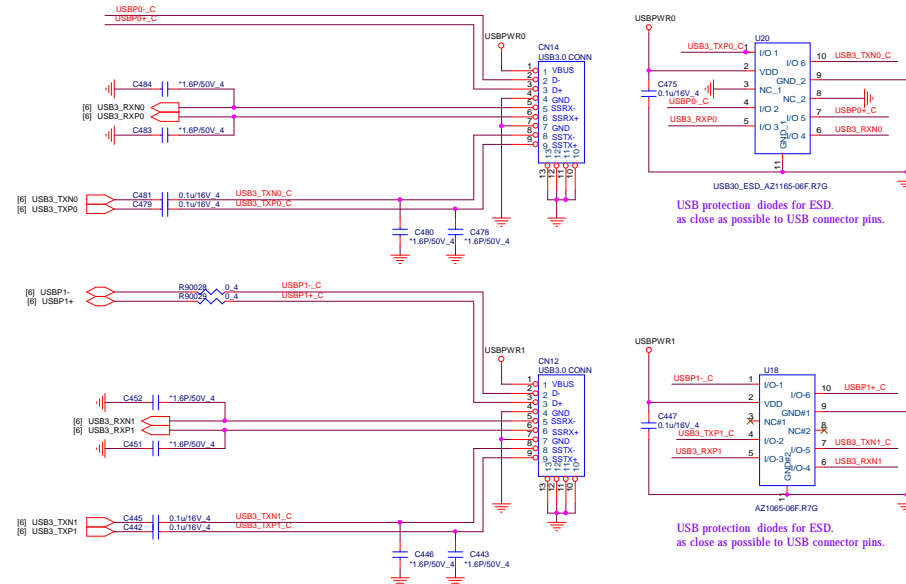
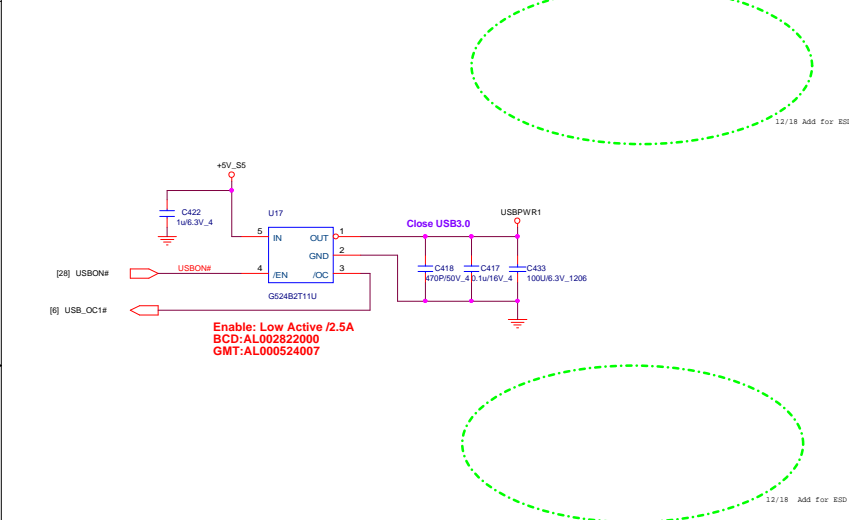
The following equation programs the typical current limit:

$$IOS_typ(mA) = 50.250 / \{RILIM_XX(k\Omega) + 0.1\}$$

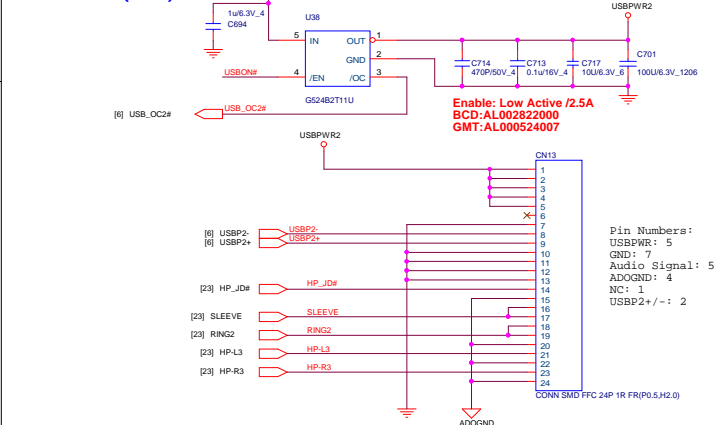
(1)

RILIM_XX corresponds to either RILIM_HI or RILIM_LO as appropriate.

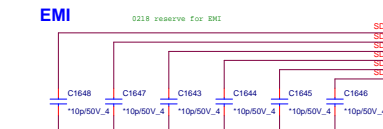
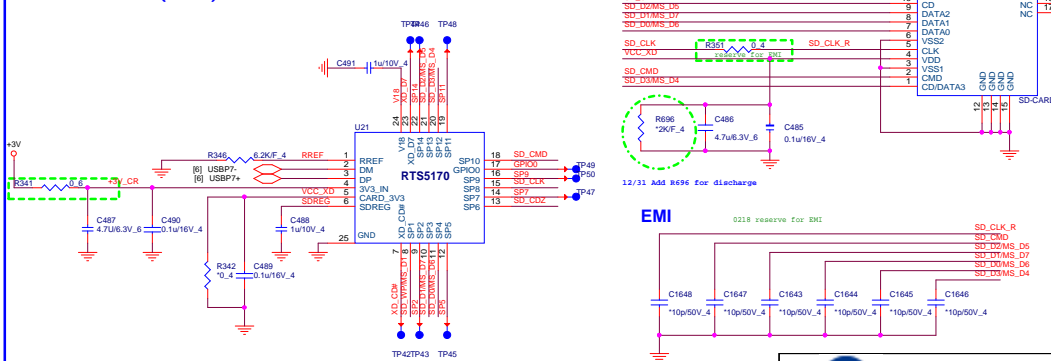
USB 3.0 Connector (UB3)

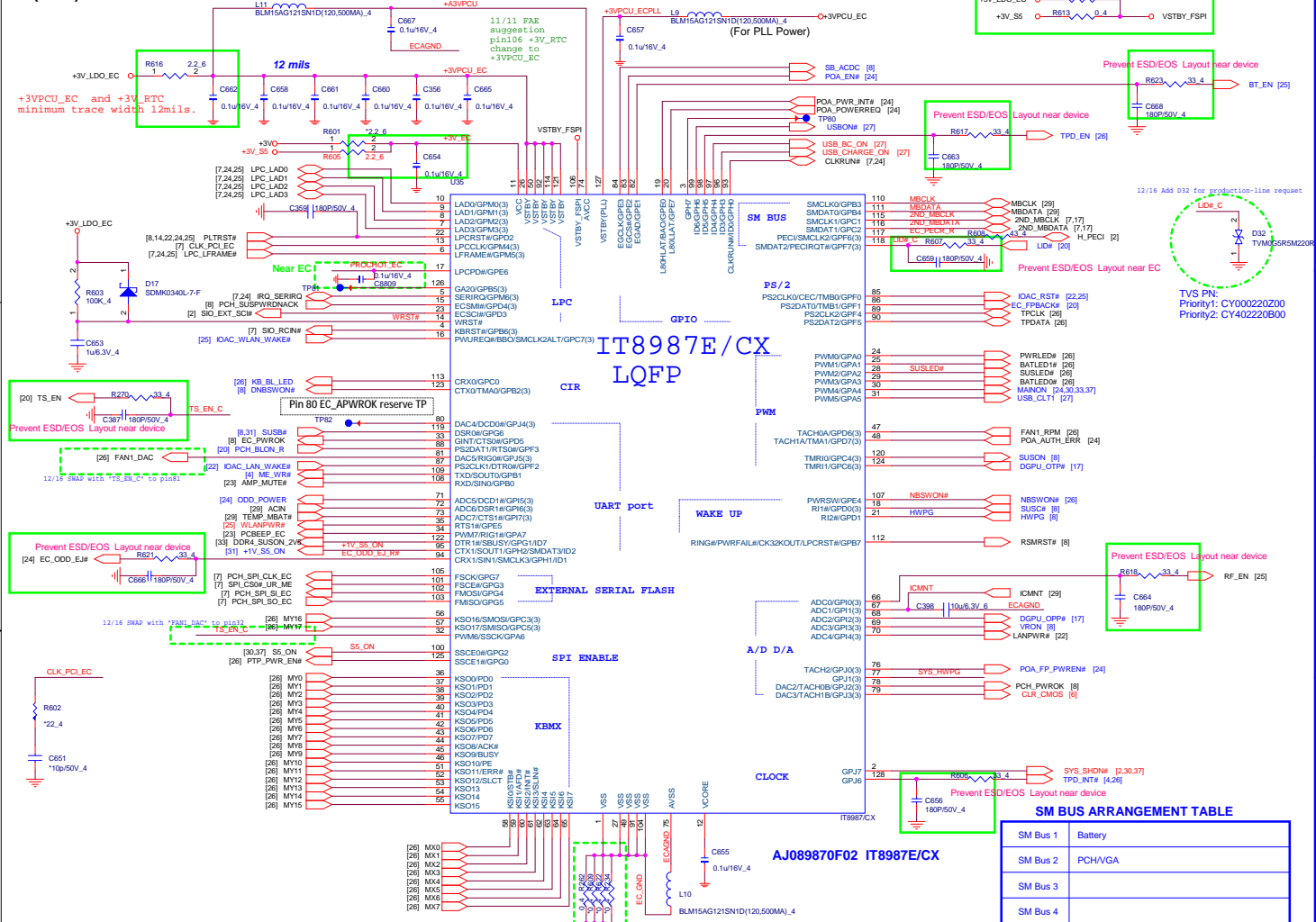


USB2.0 DB (UB2)



Card Reader (CRD)





SM BUS PU(KBC)

Battery module

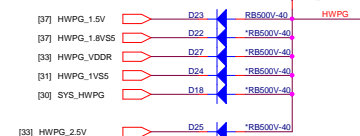
UMA& VGA SKU

Need Stuff

HWPG(KBC)

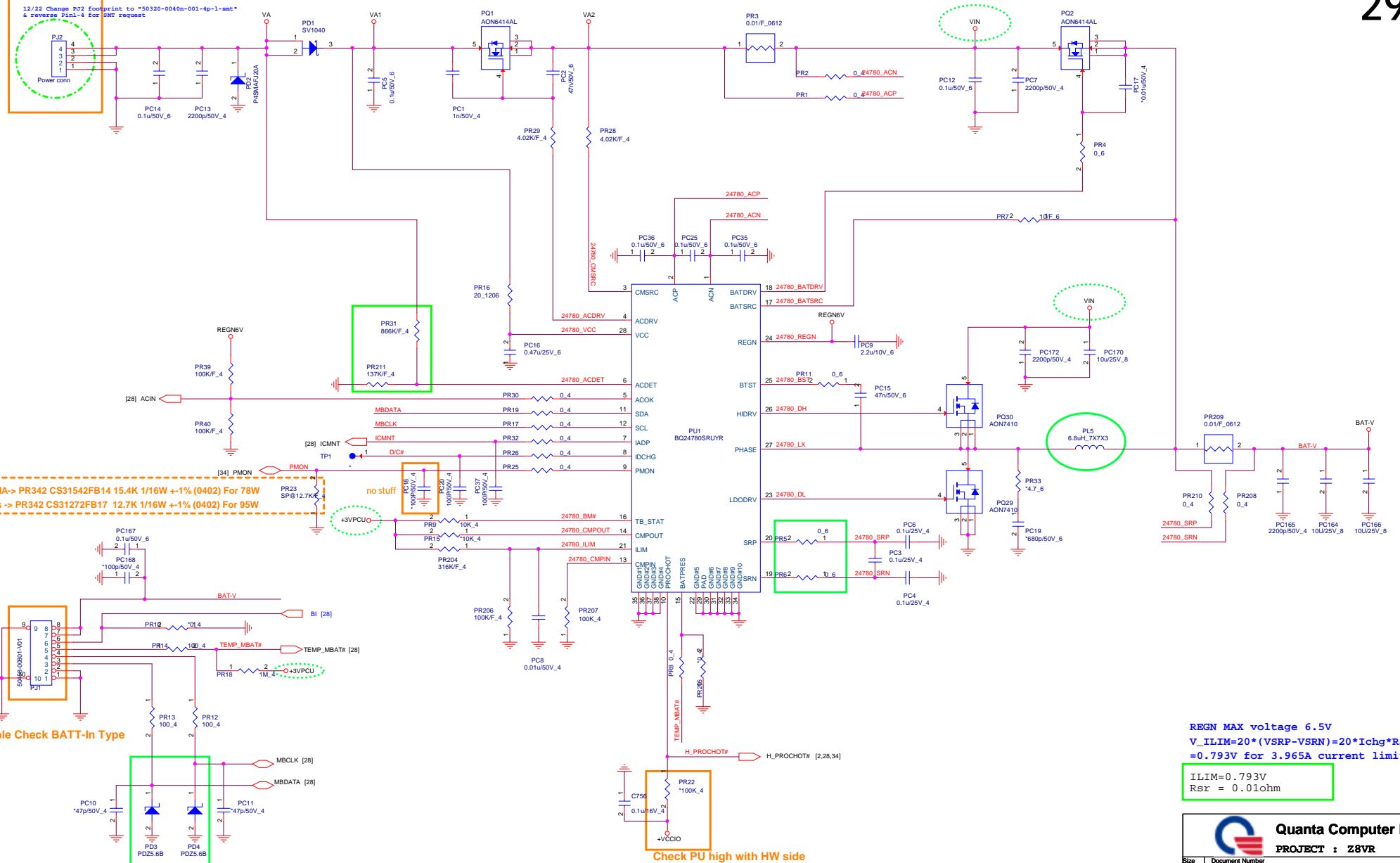
DDR=1.5V, D1 DNP and D2 POP

DDR=1.35V, D1 POP and D2 DNP

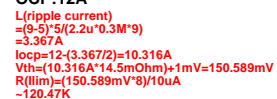


Double Check ADP-In Type

12/22 Change P02 footprint to *03320-0040n-001-4p-1-mnt* & reverse Pin1-4 for HW request



REGN MAX voltage 6.5V
 $V_{ILIM} = 20 * (V_{SRP} - V_{SRN}) = 20 * I_{chg} * R_{sr}$
 $= 0.793V$ for 3.965A current limit
 $ILIM = 0.793V$
 $R_{sr} = 0.01ohm$

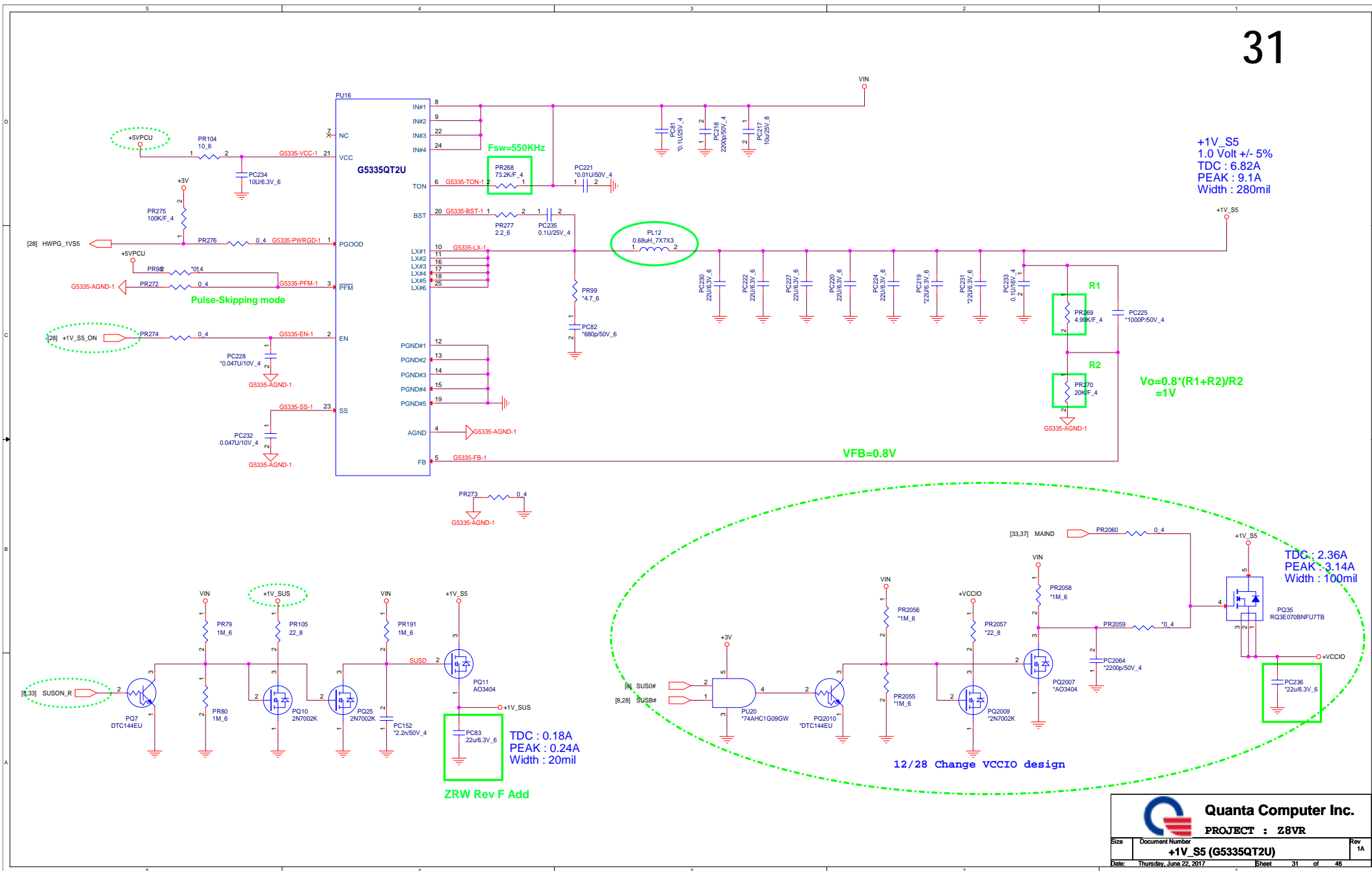


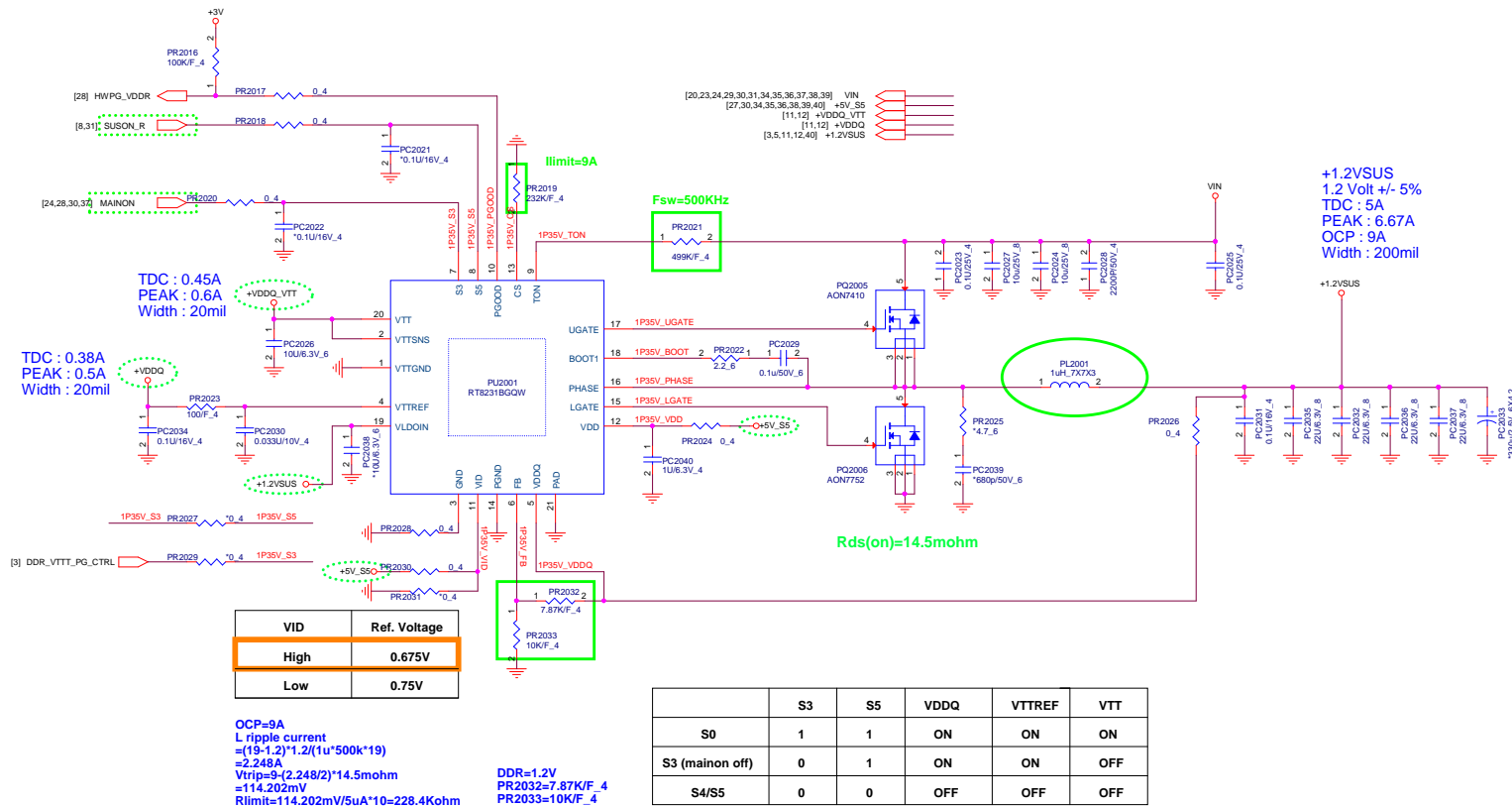
$L(\text{ripple current}) = (9-3.3) \cdot 3.3 / (2.2 \mu \cdot 0.355 \text{M} \cdot 9) = 2.676 \text{A}$
 $I_{\text{ocp}} = 10 - (2.676/2) = 8.662 \text{A}$
 $V_{\text{th}} = (8.662 \text{A} \cdot 14.5 \text{m}\Omega) + 1 \text{mV} = 126.599 \text{mV}$
 $R(\text{Ilim}) = (126.599 \text{mV}^8) / 10 \mu \text{A} = 101.279 \text{K}$

PR189 change to 9.31K for IR camera

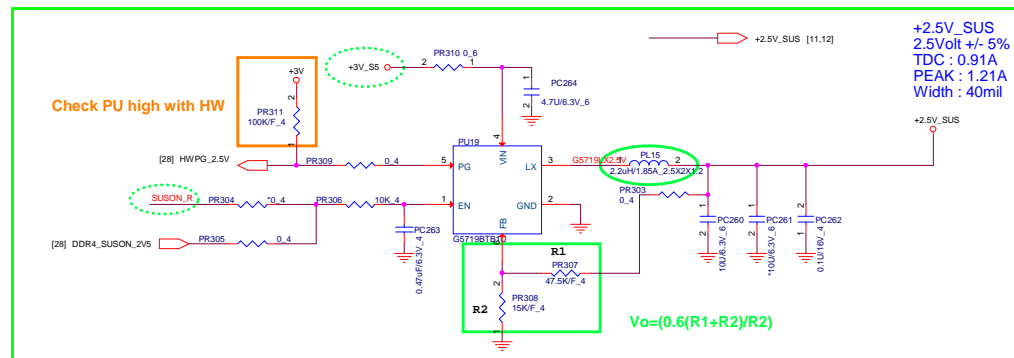


Soft-Start

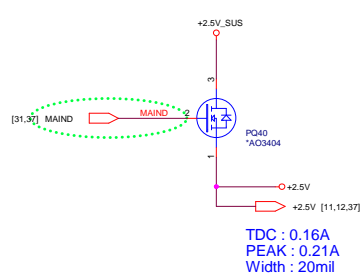




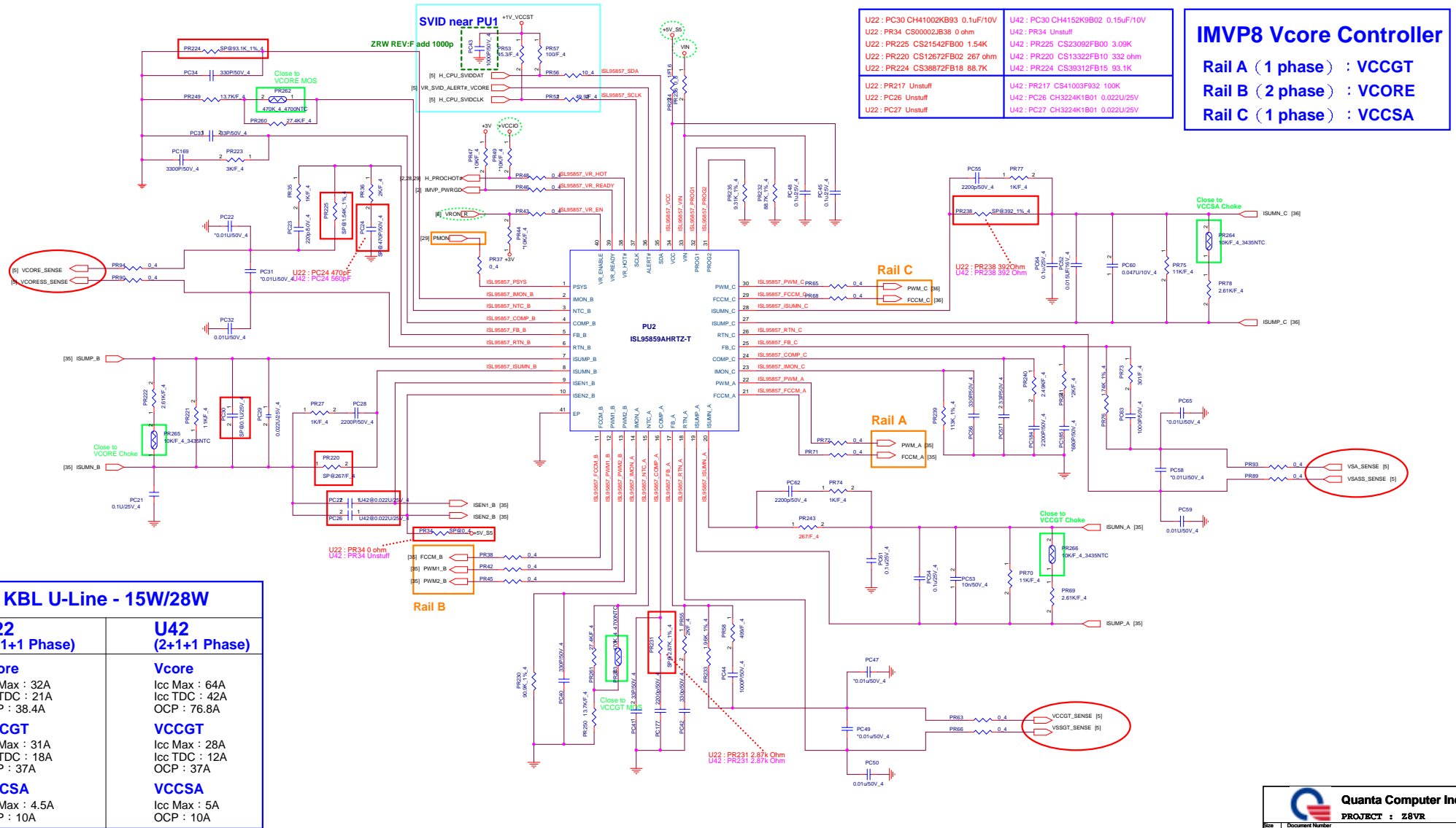
+2.5VSUS Power Rail For DDR4



10/26 Reserve +2.5V for DDR4 VDDSPD



Check PU high with HW



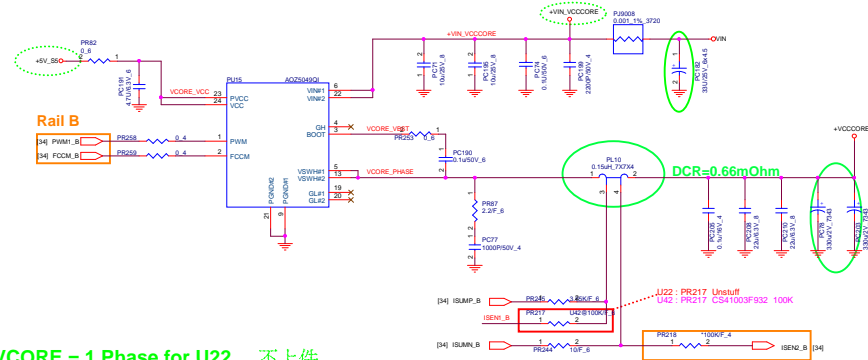
KBL U-Line - 15W/28W	
U22 (1+1+1 Phase)	U42 (2+1+1 Phase)
Vcore Icc Max : 32A Icc TDC : 21A OCP : 38.4A	Vcore Icc Max : 64A Icc TDC : 42A OCP : 76.8A
VCCGT Icc Max : 31A Icc TDC : 18A OCP : 37A	VCCGT Icc Max : 28A Icc TDC : 12A OCP : 37A
VCCSA Icc Max : 4.5A OCP : 10A	VCCSA Icc Max : 5A OCP : 10A

[26,23,24,29,30,31,33,34,36,37,38,39] VIN
 [8] +VCCORE
 [9] +VCCGT
 [27,30,33,34,36,38,39,40] +5V, 5S

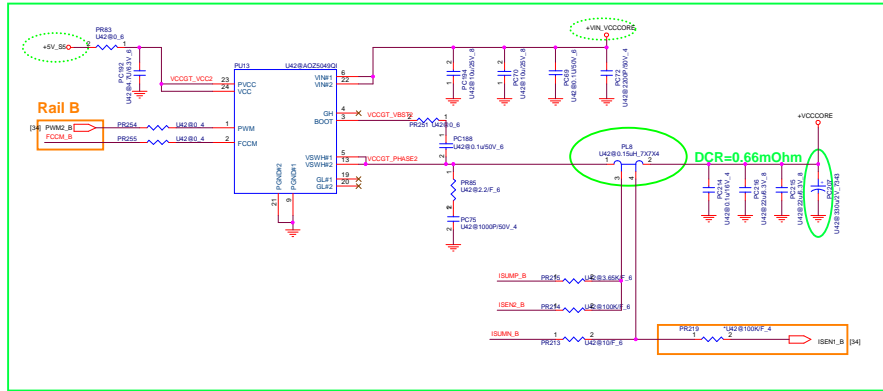
U22: PR217 Unstuff

U42: PR217 CS41003F932 100K

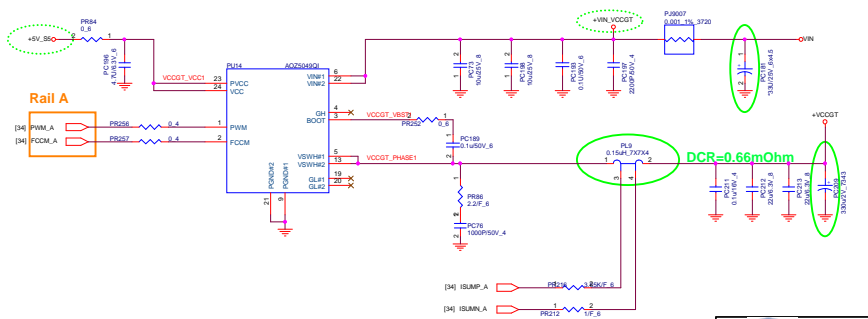
VCORE



VCORE = 1 Phase for U22 , 不上件
 VCCORE = 2 Phase for U42 , 上件



VCCGT



VCCSA

R_AC_LL : 10.3mV/A



Size	Document Number	Rev
	VCCSA (ISL95808HRZ-T)	1A
Date:	Thursday, June 22, 2017	Sheet 36 of 46

Check PU high with HW

+1.8V_S5
1.8Volt +/- 5%
TDC : 2.61A
PEAK : 3.48A
Width : 120mil

$$V_o = 0.6 \cdot (R_1 + R_2) / R_2 = 1.8V$$
$$V_o = 0.8(1 + R_1/R_2) = 1.5V$$

+1.5V
1.5Volt +/- 5%
TDC : 0.49A
PEAK : 0.66A
Width : 20mil

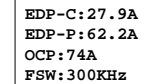
Thermal protection

Need fine tune
for thermal protect point
Note placement position
TEMP=85C

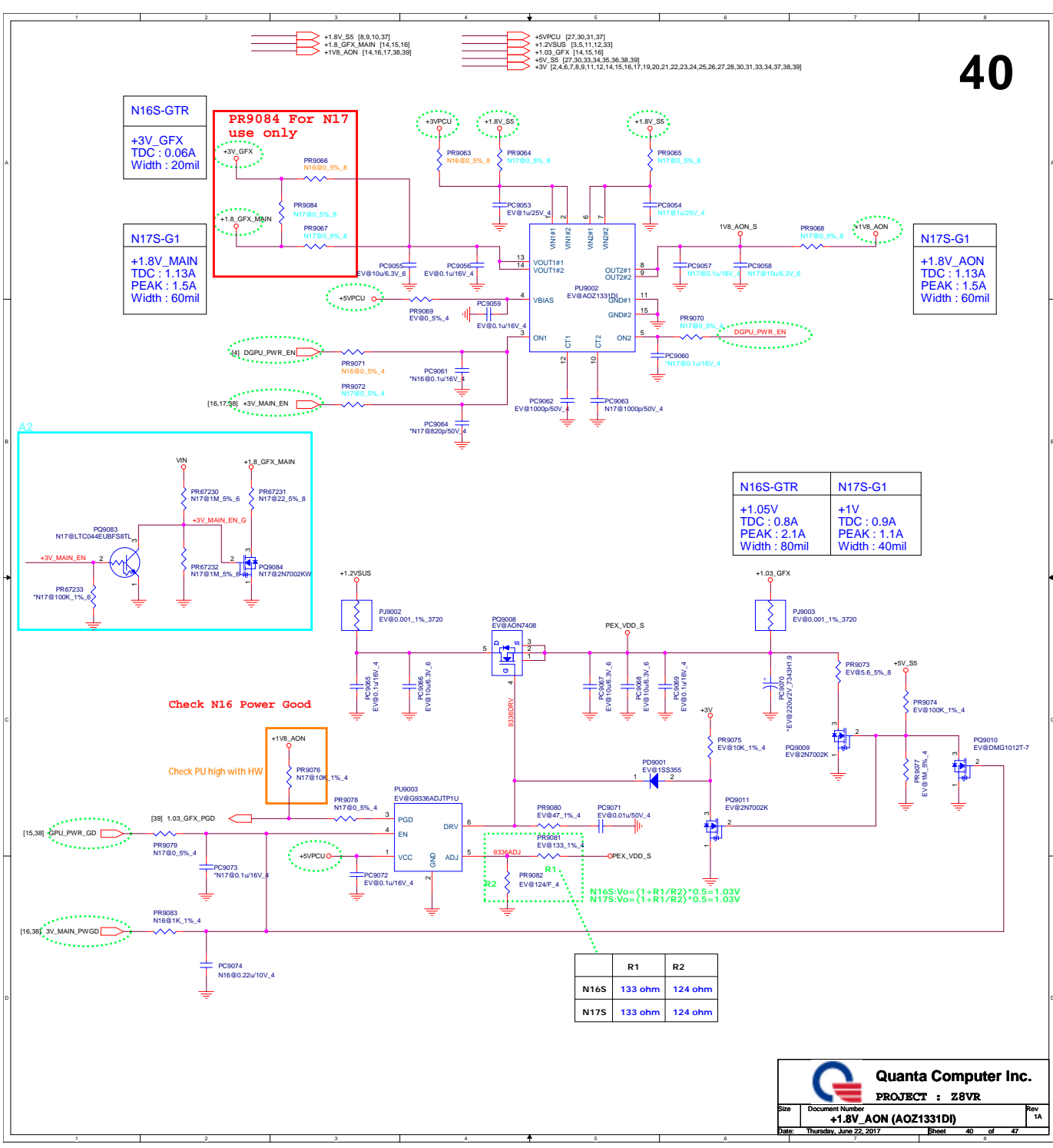
For EC control thermal protection (output 3.3V)

PR153 Change to 220 ohm for bo bo sound issue.

ZRW Rev:D Stuff



NV16 Config : B		NV17 Config : Type2+	
R1	20K	R1	6.19K
R2	20K	R2	20.5K
R3	2K	R3	4.32K
R4	18K	R4	16.5K
R5	0 ohm	R5	0.309K
C	2.7nF	C	4.7nF



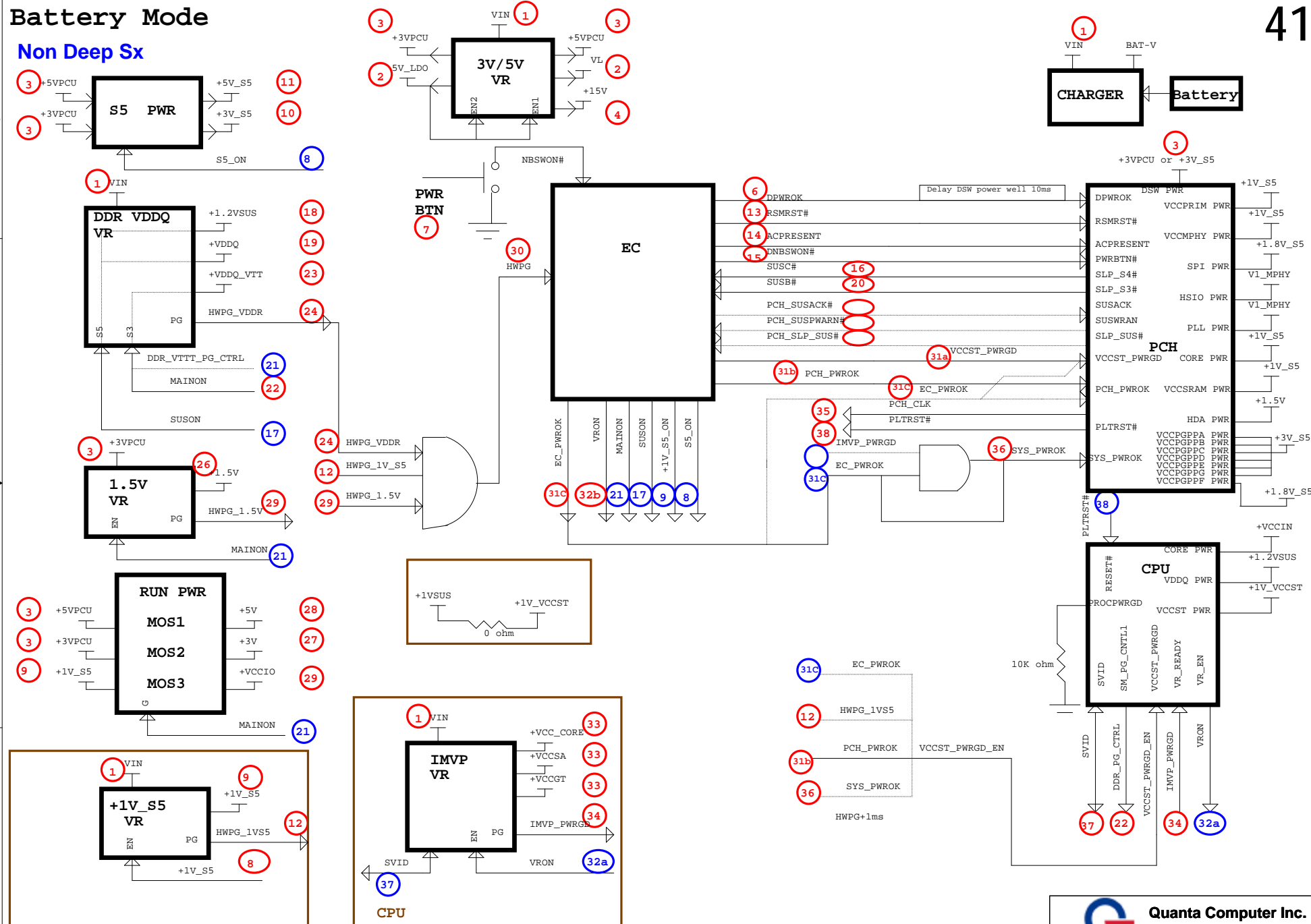
N16S-GTR	N17S-G1
+1.05V TDC : 0.8A PEAK : 2.1A Width : 80mil	+1V TDC : 0.9A PEAK : 1.1A Width : 40mil

	R1	R2
N16S	133 ohm	124 ohm
N17S	133 ohm	124 ohm

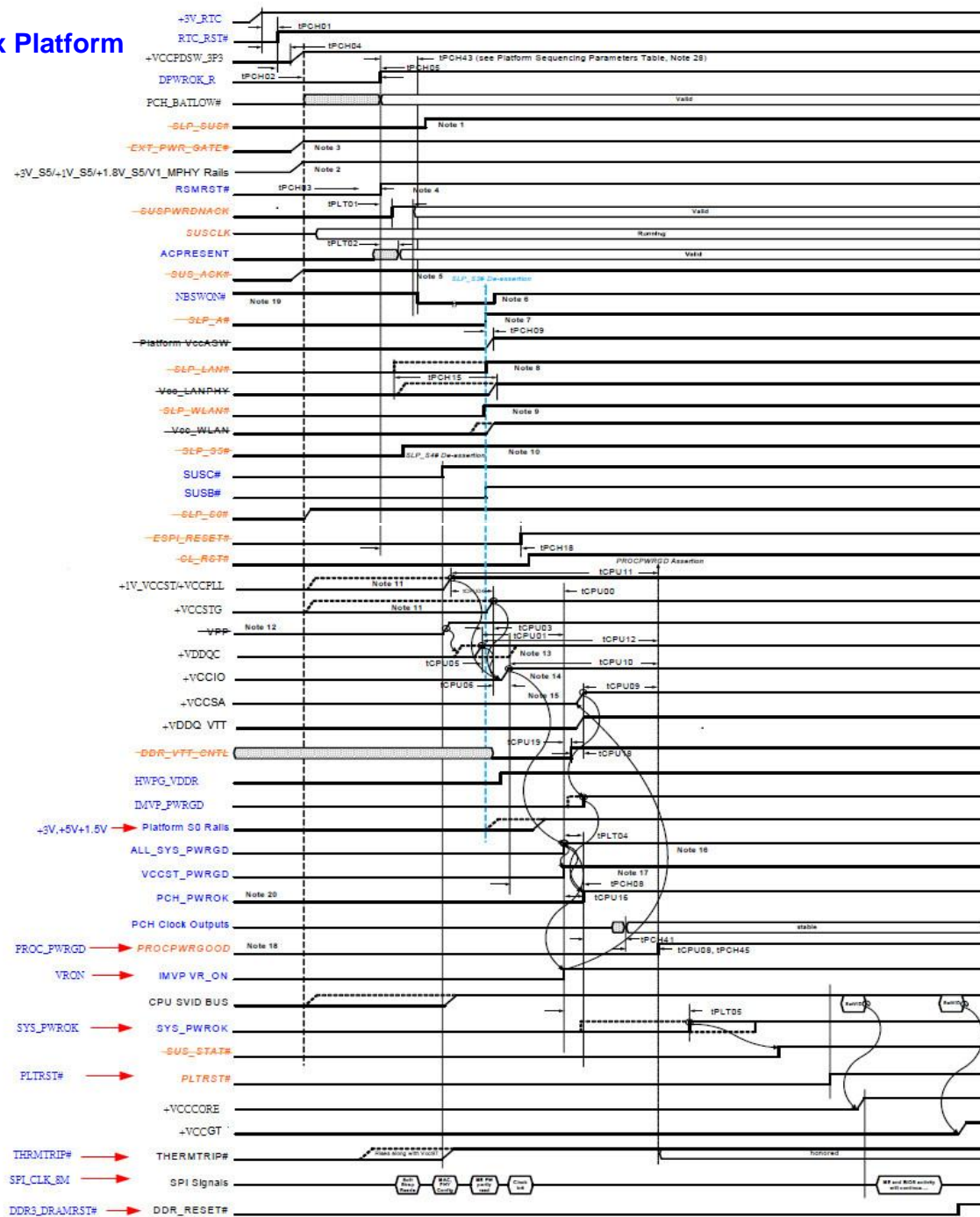
Battery Mode

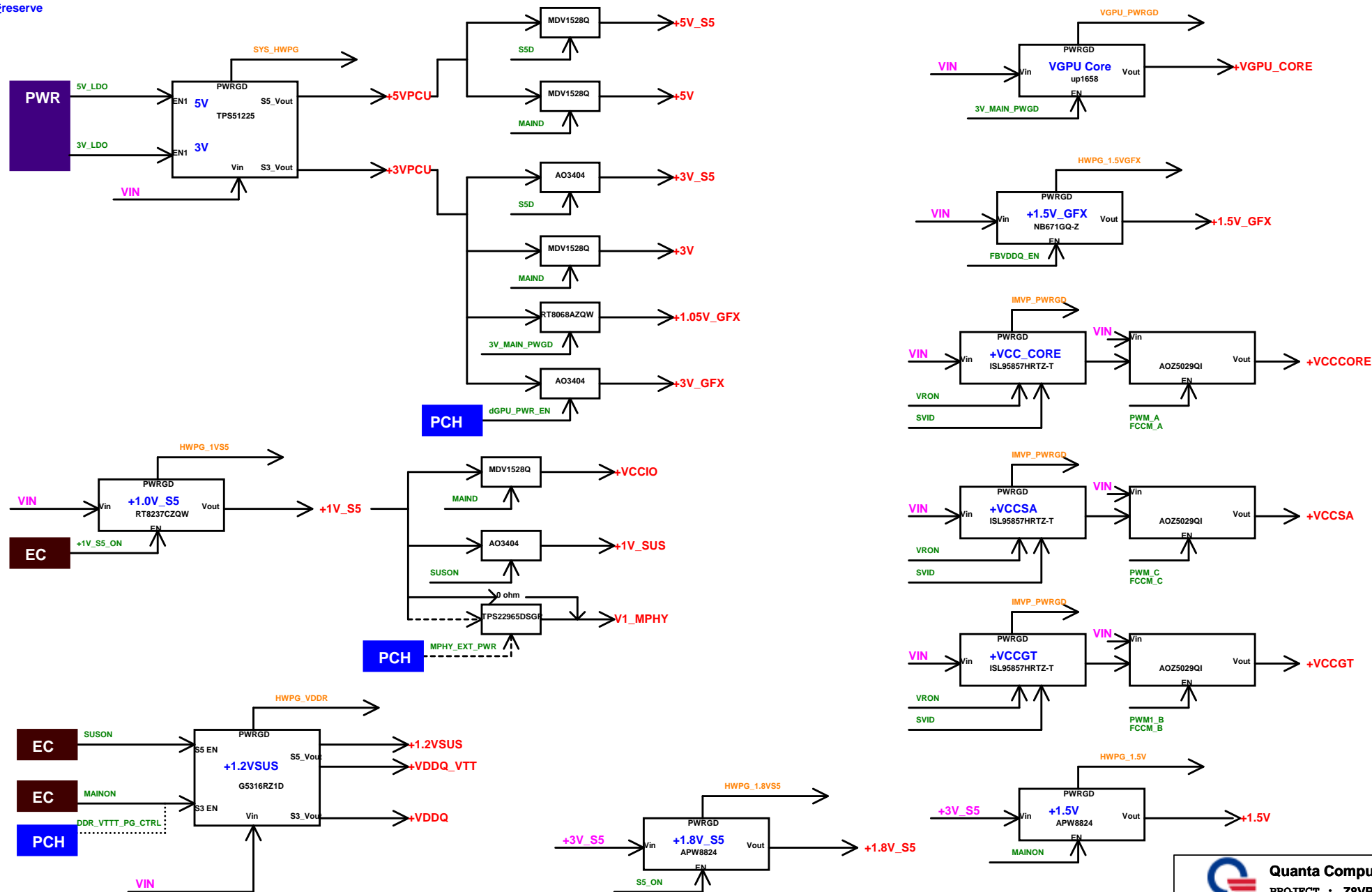
Non Deep Sx

41

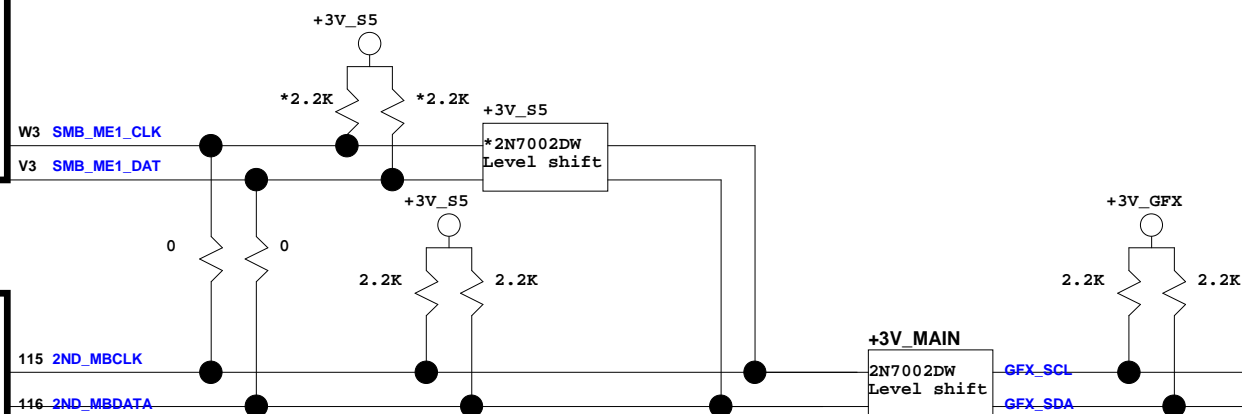
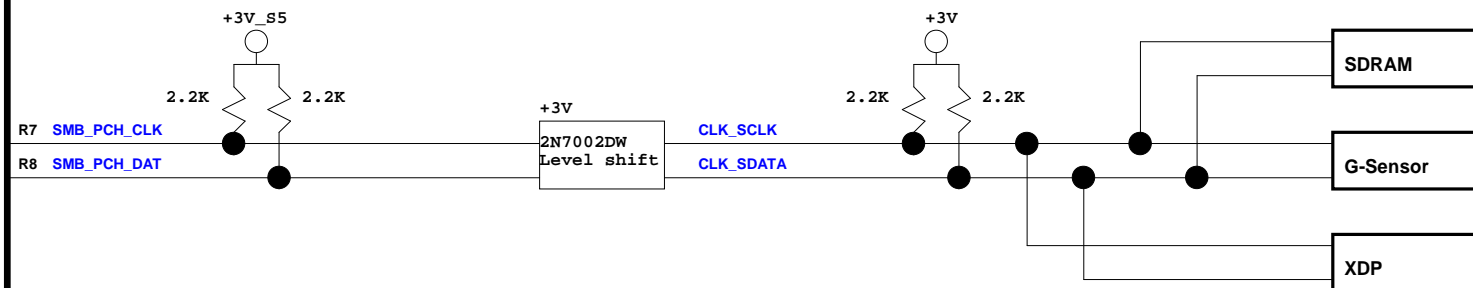
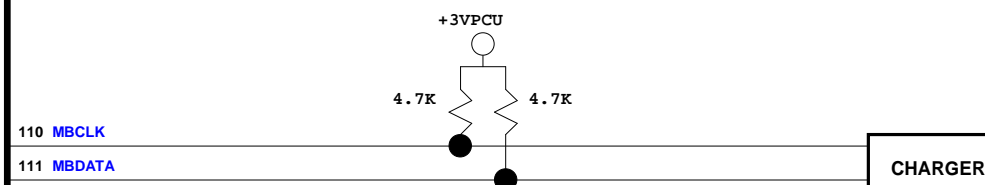


Skylake U Non-Deep Sx Platform Power on sequence






Skylake U

EC
IT8987CX

Model	Date	CHANGE LIST
Z8VR REV:A	03/14	First release
Z8VR REV:B	03/16	Change SW3 Footprint to Sw-ds-a40e-4p-smt for SMT issue Remove C460/C461 for 16G memory module can't power on issue Change SPI ROM GGD 16M P/N to GD25B127DSIGR, original PN is EOL
	03/28	according to Intel DG to unstuff R8748,R8749 and R417.
	04/28	label PR23 as sp@(UMA and DIS value are different)
Z8VR REV:C	05/15	Change 0 Ohm to shortpad add EV# for PQ9002 value that no need to stuff on UMA SKU
	06/01	Change for Power Noise issue 1.Add PC181 with 33uF in +VIN_VCCGT net 2.Change PC210,PC216 from 22 uF to 47 uF 3.Change PC208,PC212 from 22uF to no stuff

 Quanta Computer Inc. PROJECT : Z8VR Change list	DOC NO.	PROJECT MODEL :	Z8VR	APPROVED BY:		DATE:
		PART NUMBER:		DRAWING BY:		REVISION:

